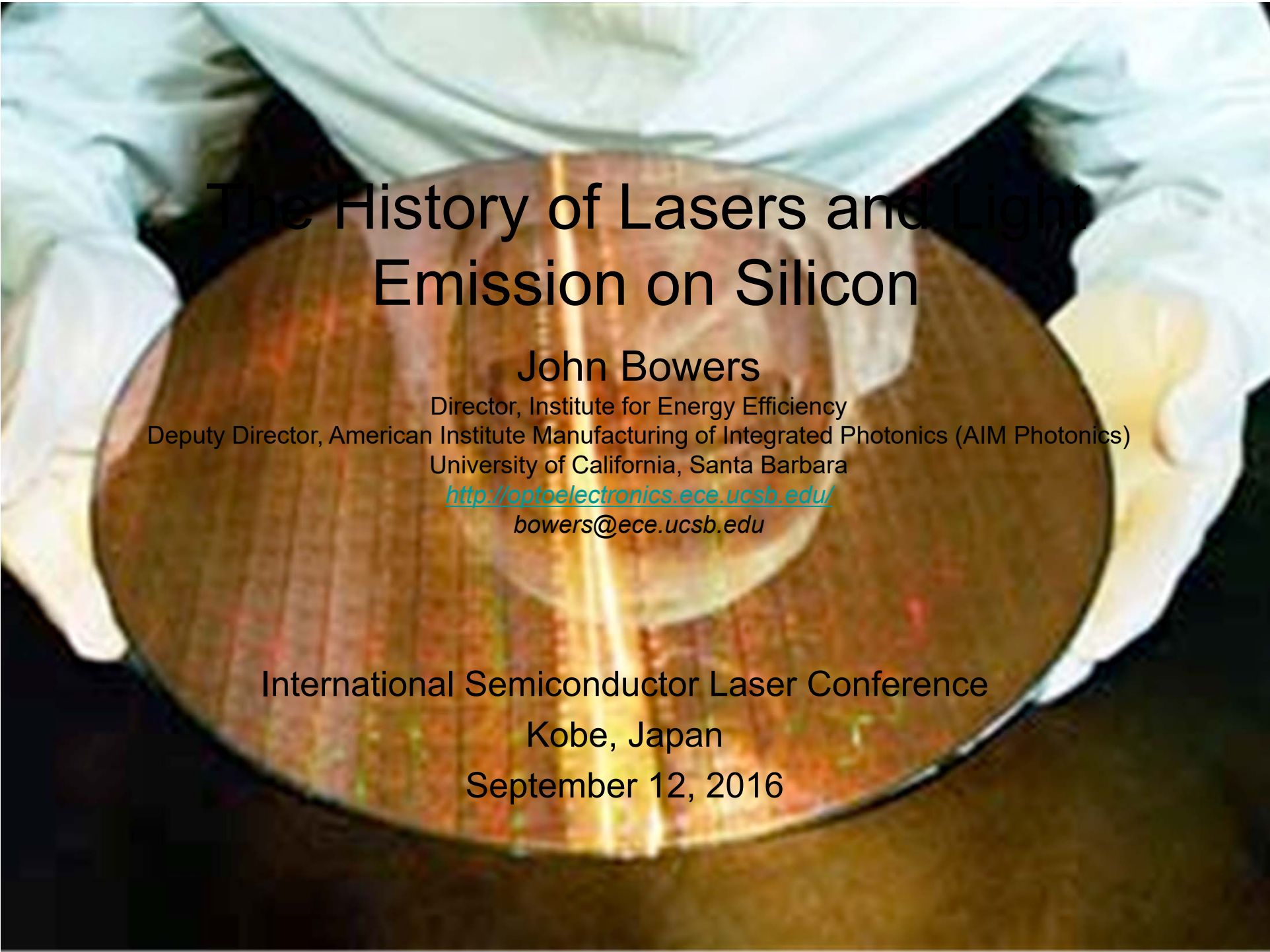




The History of Lasers and Light Emission on Silicon

John Bowers

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International Semiconductor Laser Conference
Kobe, Japan
September 12, 2016

Why use Silicon Substrates?

- Cheaper substrates
- Larger substrates (>300 mm)
- Large fabrication infrastructure (32 nm 300 mm fabs)
- Improved process control-critical for large scale integration.

UCSB Why use Silicon Substrates/Waveguides?

- Cheaper substrates
- Larger substrates (>300 mm)
- Large fabrication infrastructure (32 nm 300 mm fabs)
- Improved process control-critical for large scale integration.
- Lower loss waveguides: <0.3 dB/cm
- Reduced two photon absorption (100x less)
- Higher thermal conductivity (κ) of
 - Waveguides (Si has 30x higher κ than InGaAsP)
 - EAMs or PD Absorbers: Ge has 16x higher κ than InGaAs

Why not use Silicon?

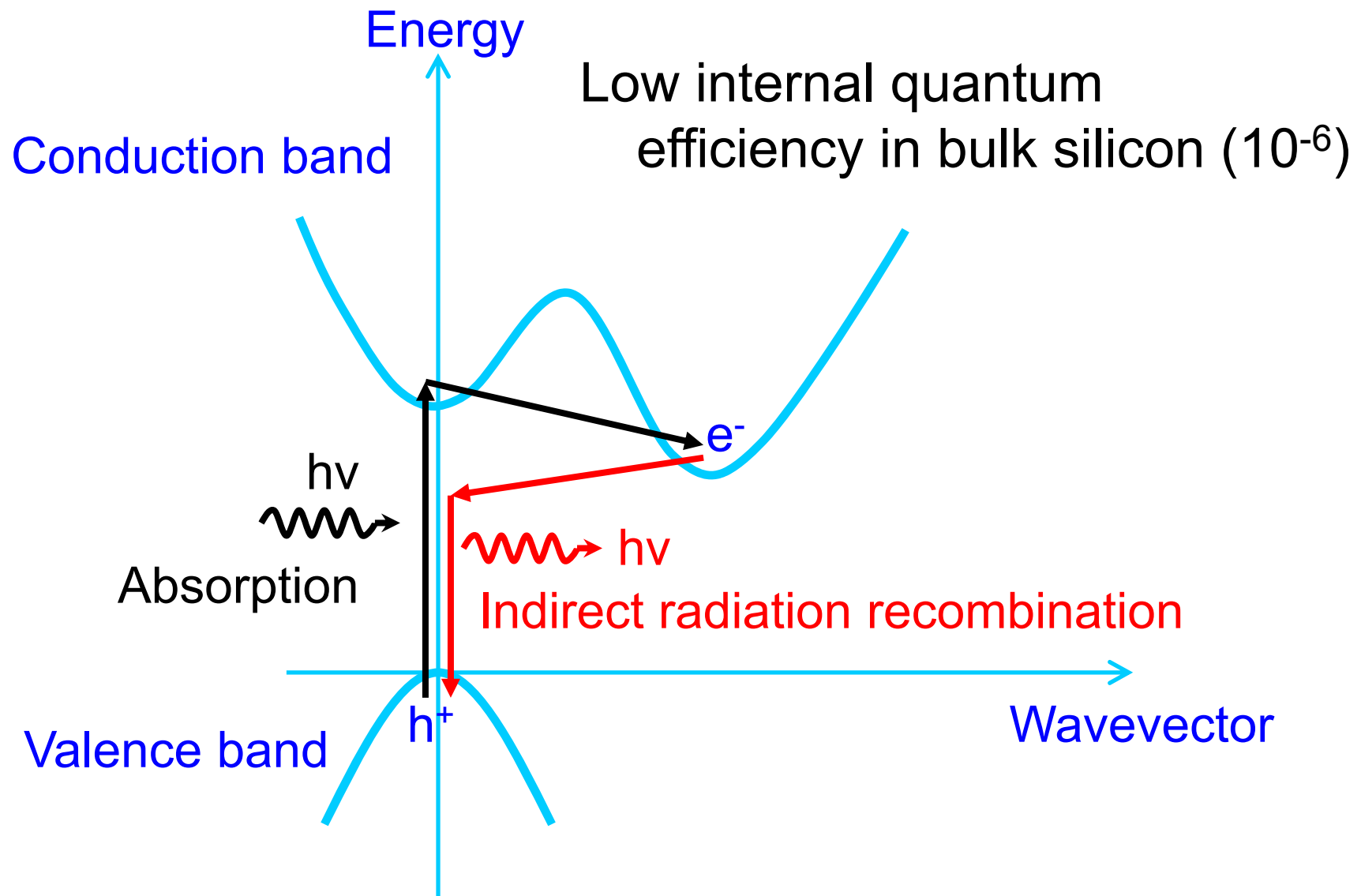
- Indirect band gap - inefficient for light emission
- Not electro-optic

Why not use Silicon?

- Indirect band gap - inefficient for light emission
- Not electro-optic

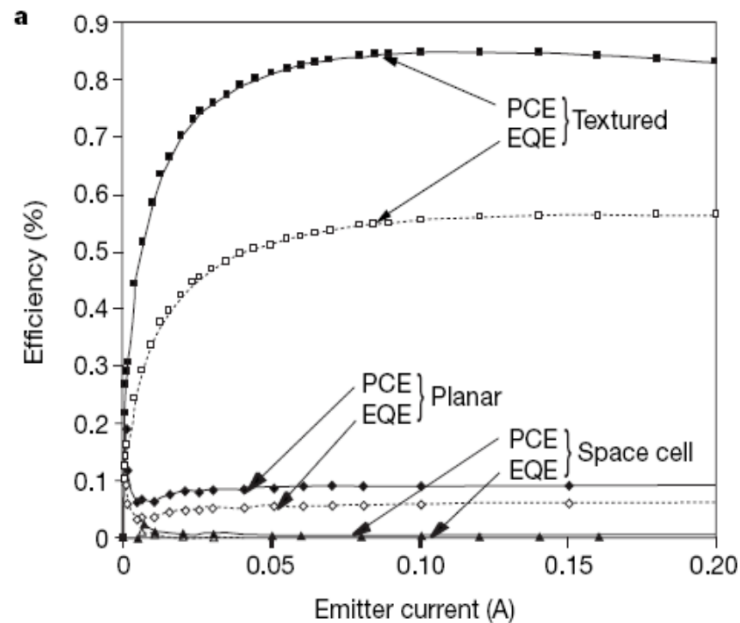
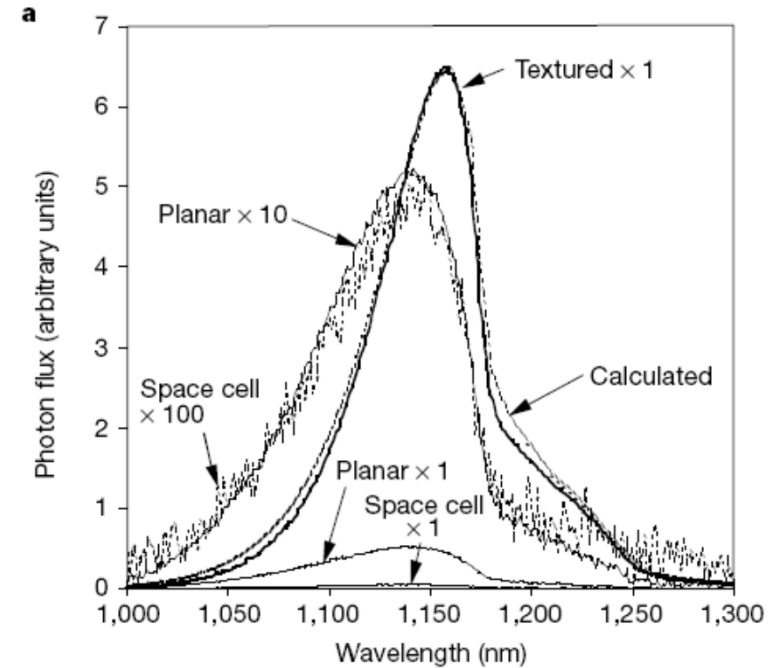
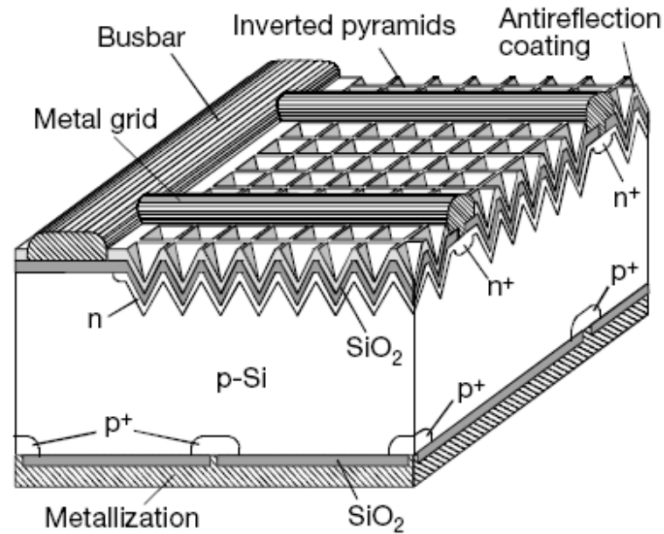
Solvable problems

Silicon light emission – limits

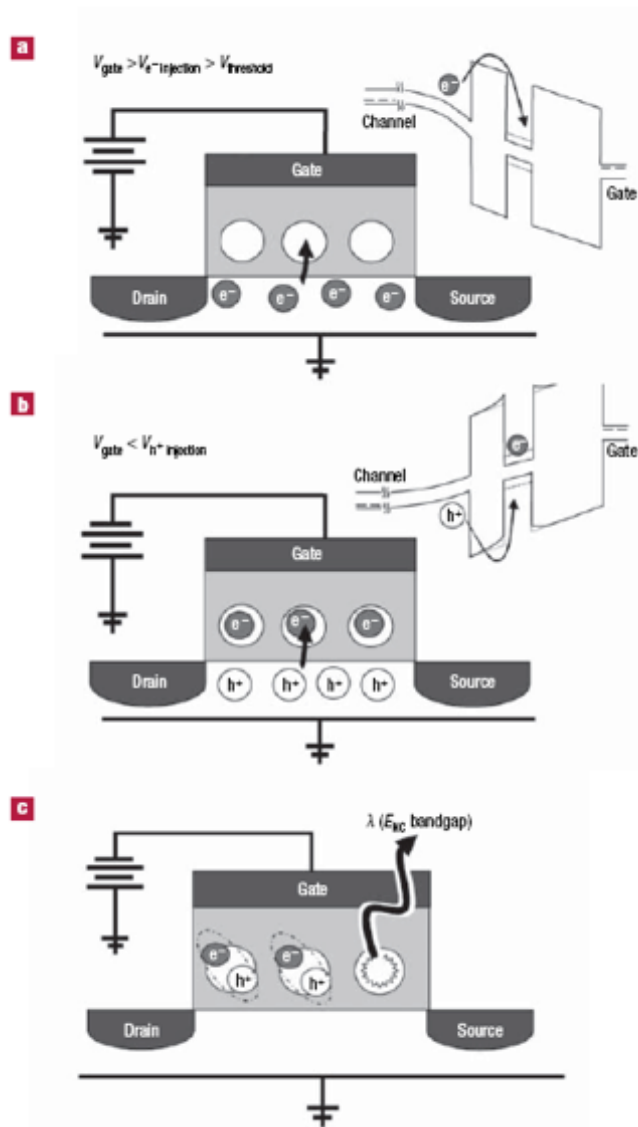


- Bulk silicon
- Low dimension Silicon
 - Silicon nanocrystal
 - Periodic nanopatterned crystalline silicon
- Er dopants
- Raman laser (UCLA/Intel)
- Another material for gain (heterogeneous approach)
 - Epitaxial
 - Ge
 - GeSn
 - Quantum Dot
 - Pillars
 - Bonding
 - Dice level
 - Wafer level (BCB or Molecular)

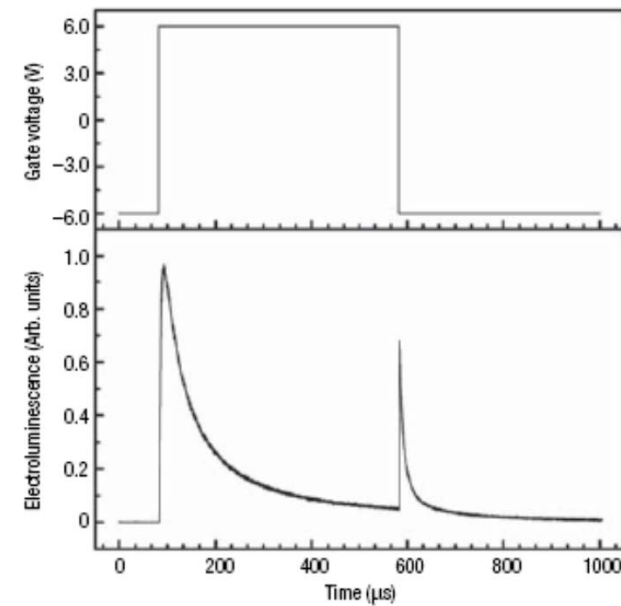
Bulk silicon LED

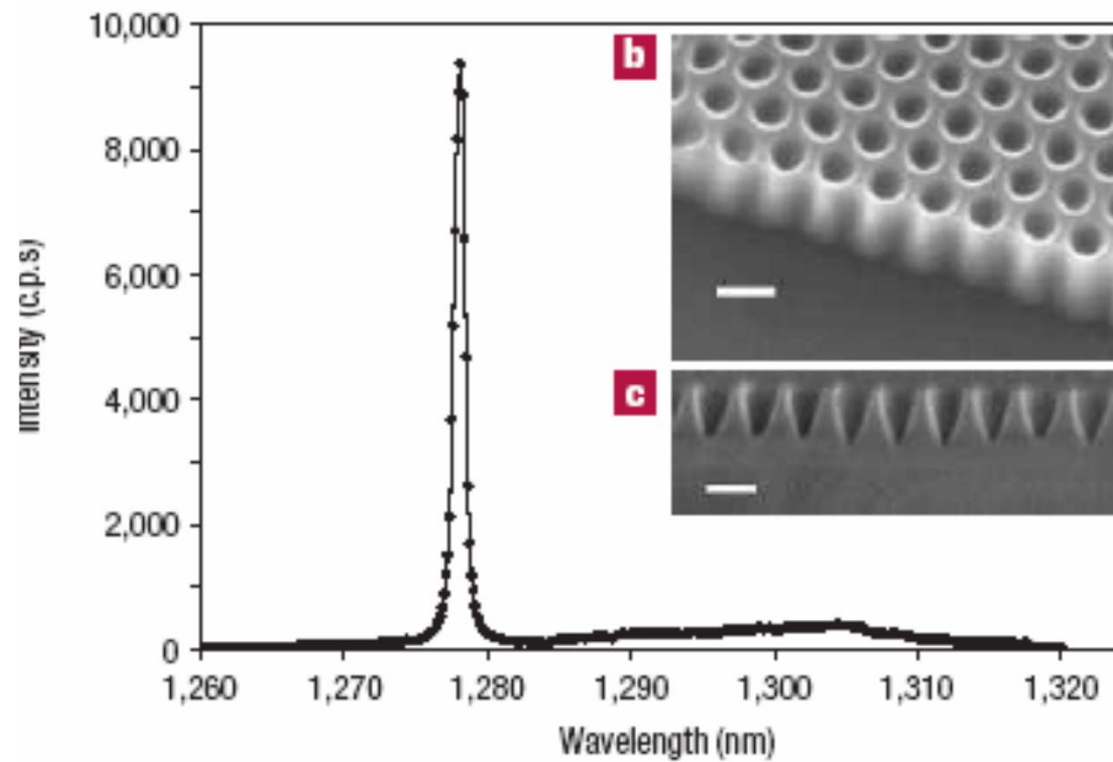


Solar cell forward bias
<1% external quantum efficiency

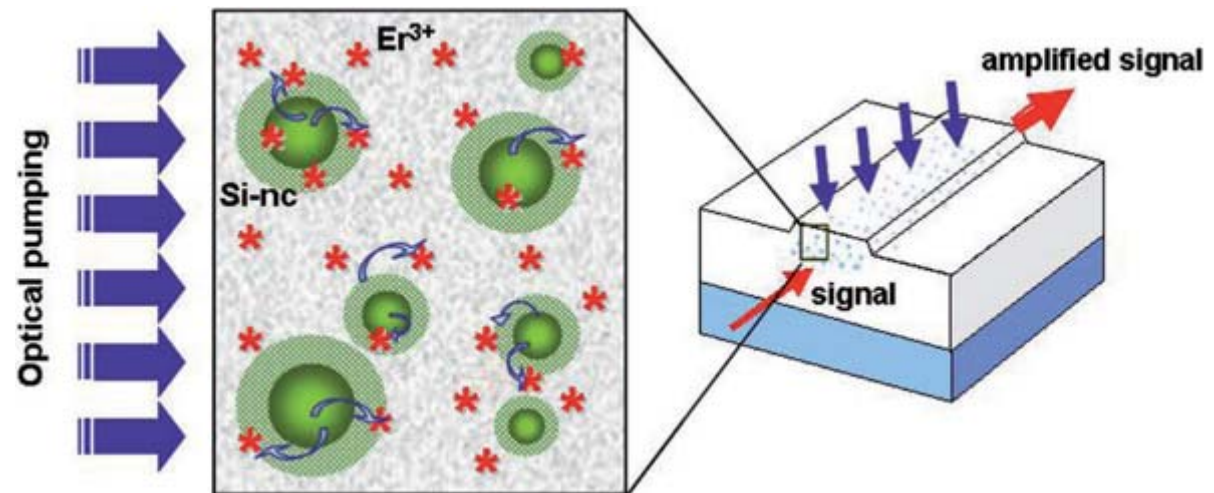
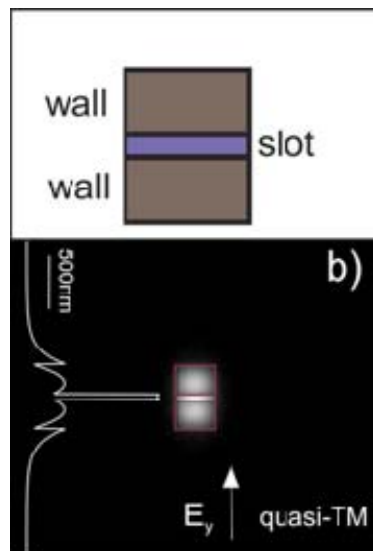


Sequential injection of electron and hole

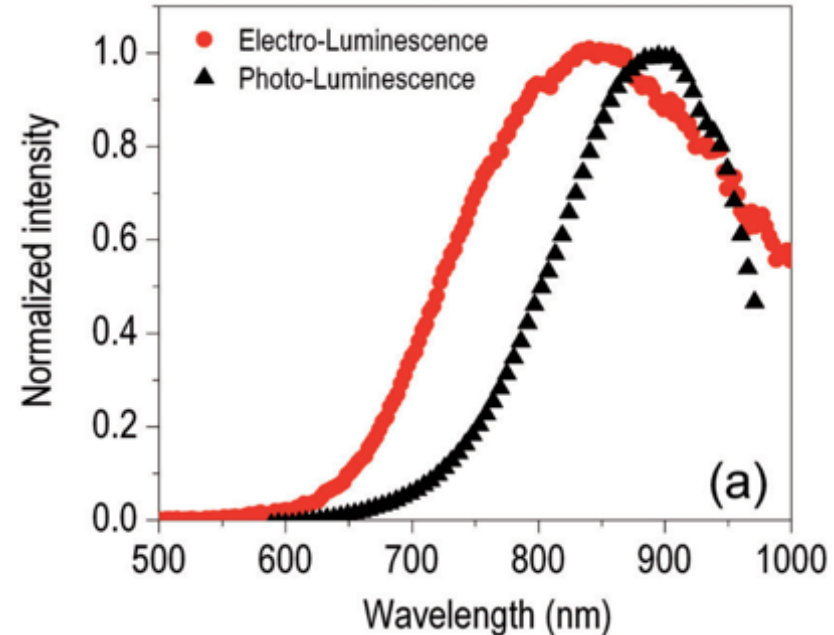
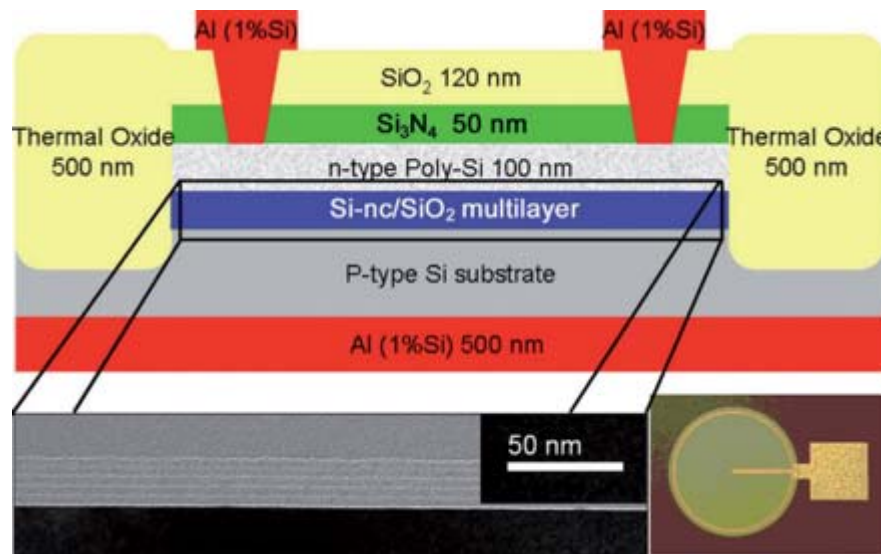


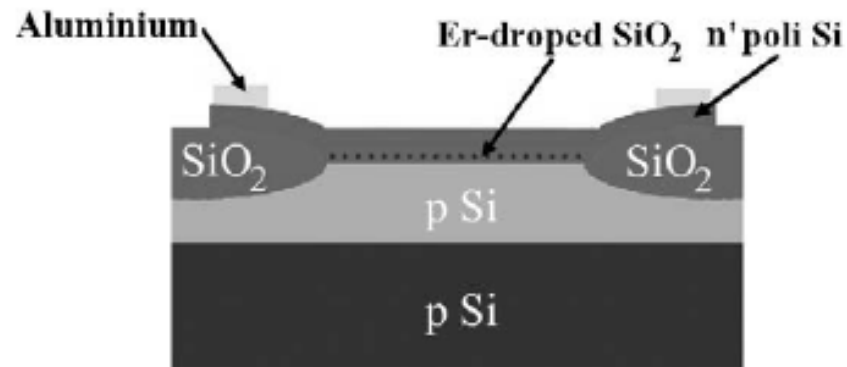


- Si-nc embedded in SiO_2 can provide optical gain (red wavelengths);
- Slot waveguides provide high SiO_2 confinement and small cross-section;
- Si-nc creates localization of injected carriers at luminescent centers (Er^{3+} for infrared)

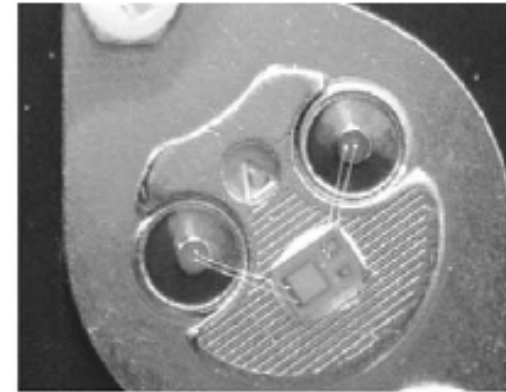


- EL power efficiency values for LED devices:
 - 0.01–0.03% for pure Si-nc;
 - 0.2–0.3% for rare-earth ion doped
- For high EL efficiency: bipolar injection needed
 - issue: electron tunneling barrier $\ll$ hole barrier





(a)



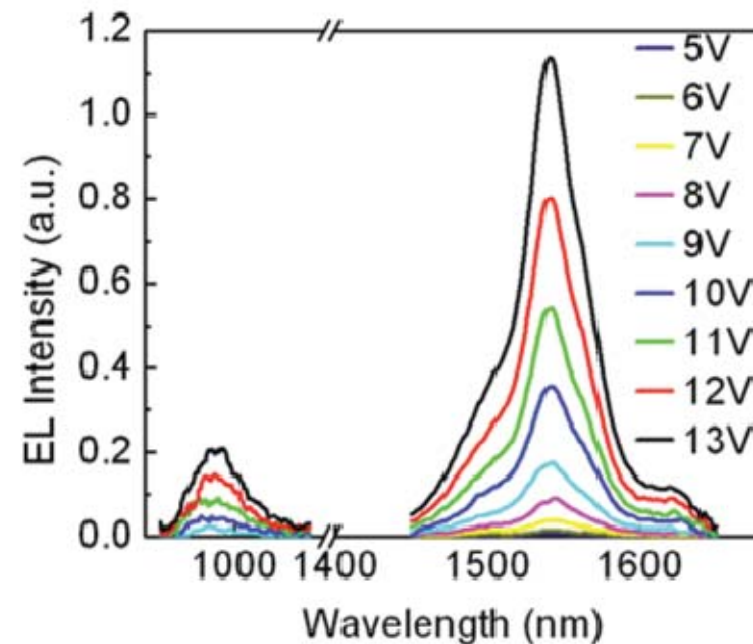
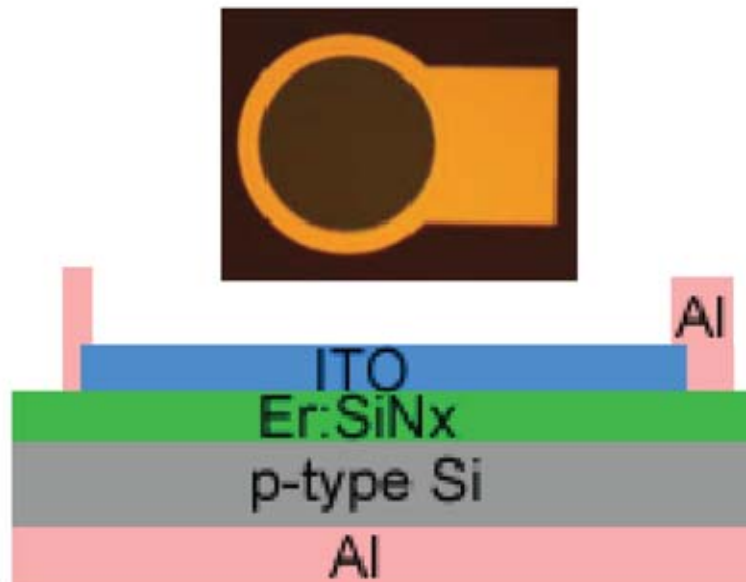
(b)

Table 1

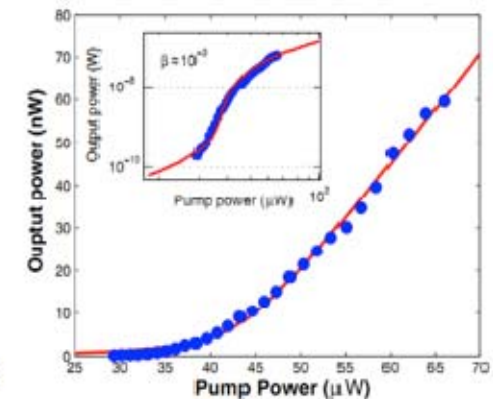
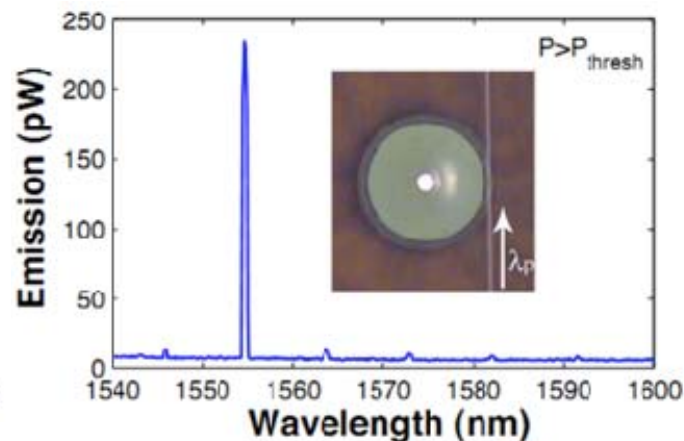
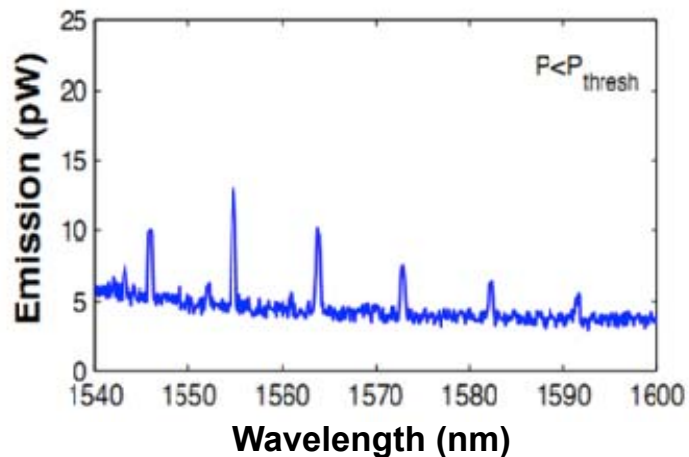
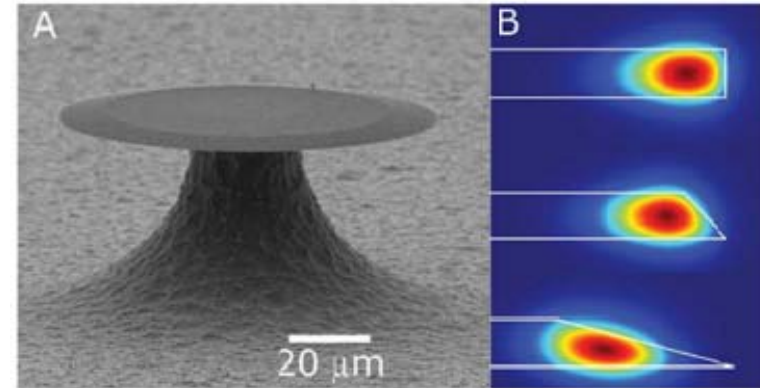
Emission wavelength, cross-section and external quantum efficiency of MOS devices with rare-earth doped gate dielectric

Rare earth	λ emission (nm)	σ (cm ²)	η_{ext} (%)
Erbium	1540	1×10^{-14}	10
Terbium	540	4×10^{-15}	10
Ytterbium	980	1×10^{-15}	0.1

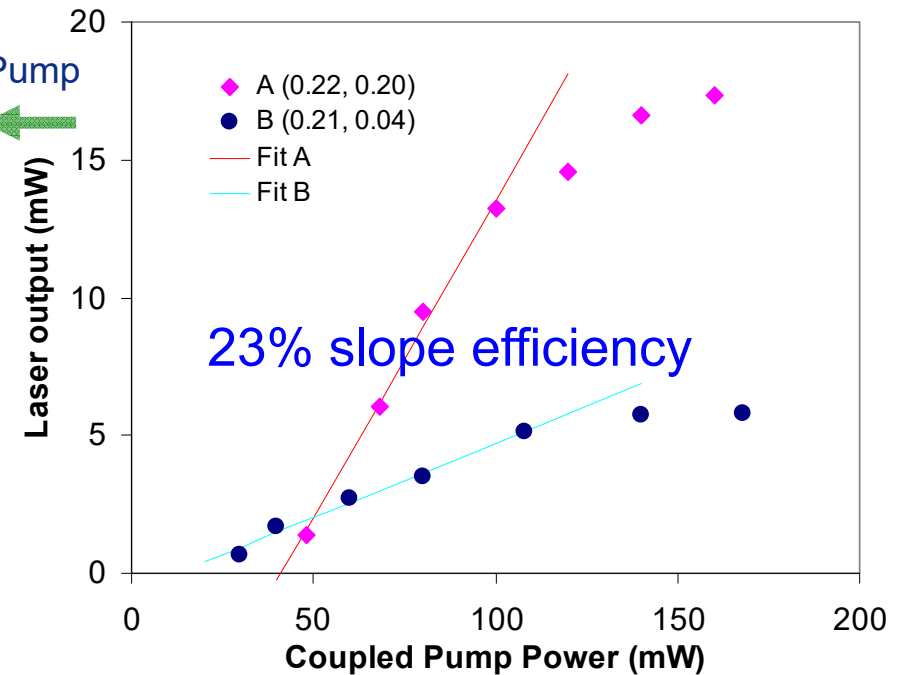
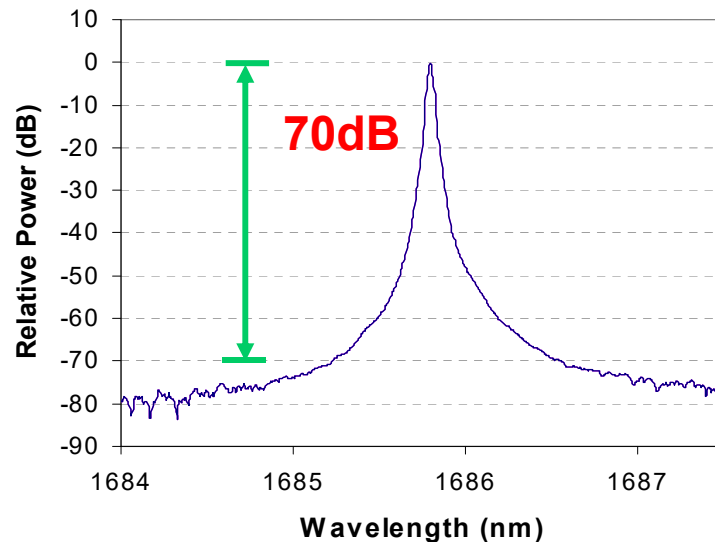
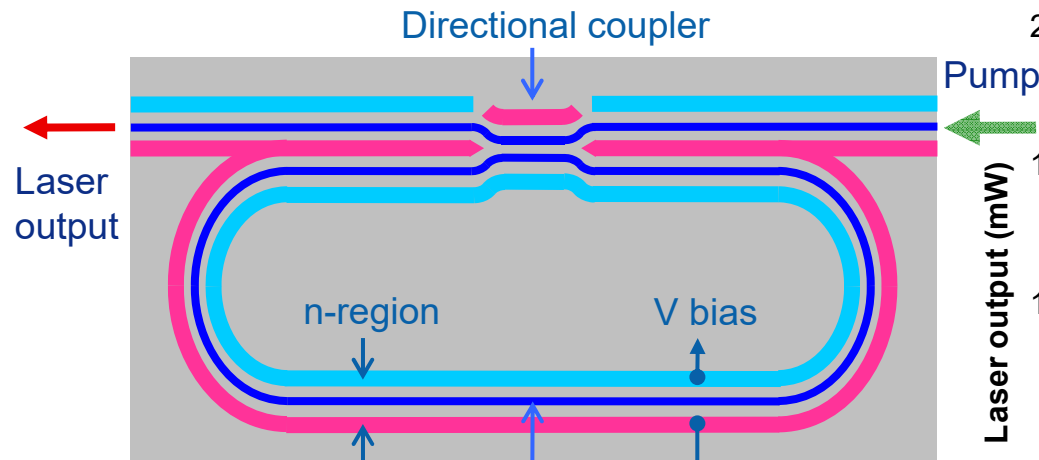
- EL centered at 1535 nm ($\text{Er } ^4\text{I}_{13/2}$)
 - Small peak at 980 nm ($\text{Er } ^4\text{I}_{11/2}$)



- SiO_2 microdisk resonator on silicon;
- whispering gallery-type mode;
- $^4\text{I}_{15/2} \rightarrow ^4\text{I}_{13/2}$ transition @ 1450 nm, lasing @ 1550 nm
- pump threshold 43 μW



CW Ring Raman silicon laser

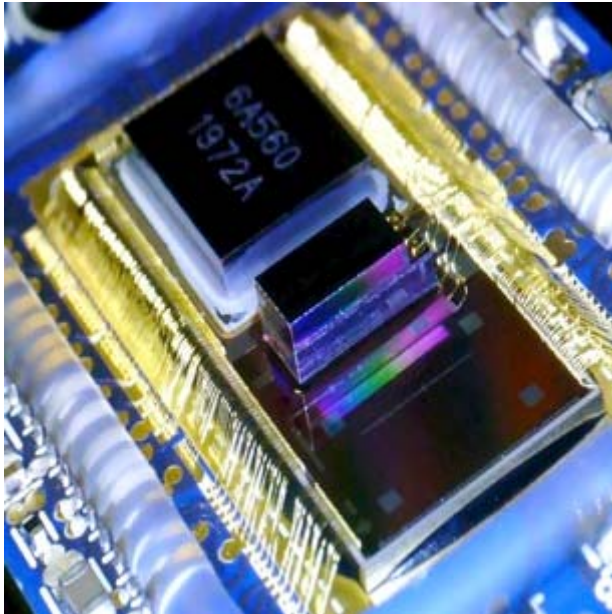


A pump laser is still needed

Heterogeneous Approaches: Use another material for gain

- Solder InP lasers to CMOS (Lightwire, Kotura, Luxtera)
- Epitaxial growth on Si substrate
 - Strained Germanium (MIT)
 - SiGeSn (AFRL, U. Mass., Arizona)
 - Quantum Dot (UCSB, UCL, HKUST, Michigan)
 - MOCVD nanopillars on Si (UC Berkeley)
- Process InP layers after CMOS (HELIOS)
- Bonded III-V layers on Si substrate
 - BCB (Ghent/IMEC)
 - Molecular (UCSB, Intel, Caltech, TIT, Hewlett Packard)

Luxtera: 4x26 Gbps PSM-4 Chipset & QSFP28 Module

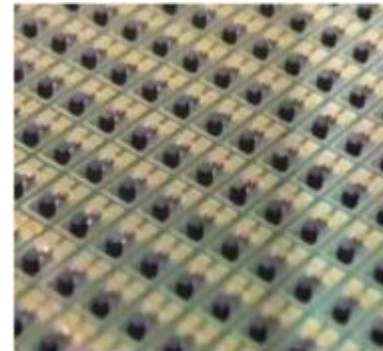
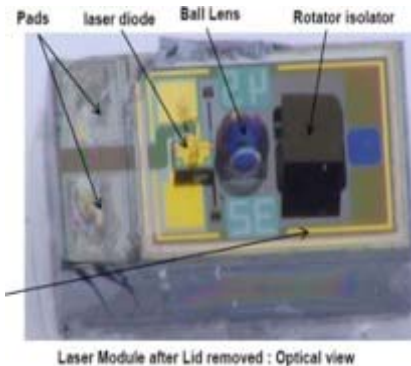
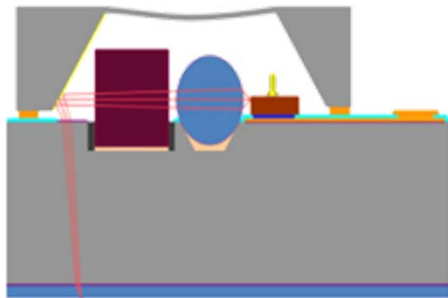
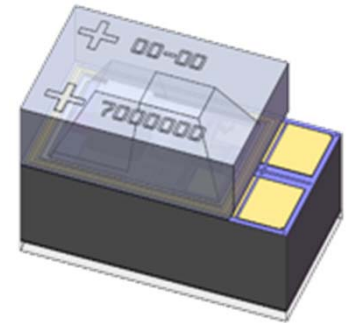


Si Photonics IC (based on 1310 nm library)

- MZI High Speed Modulators
- Ge High Speed Photodetectors
- Ge monitor PDs for control and monitoring
- BIST (Optical High-Speed loopback)
- Photonics assembly features

Single light source (1310 nm)

- Based on 1310 nm InP/InGaAsP DFB laser diode



Flip Chip Assembly of III/V Components on Si

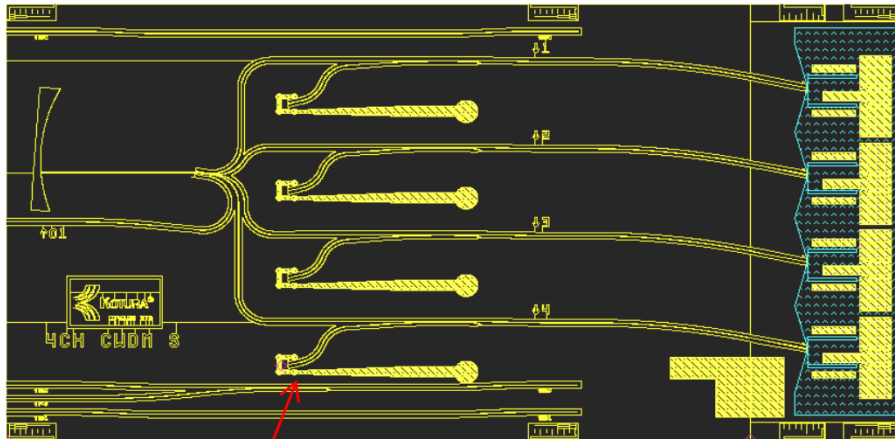
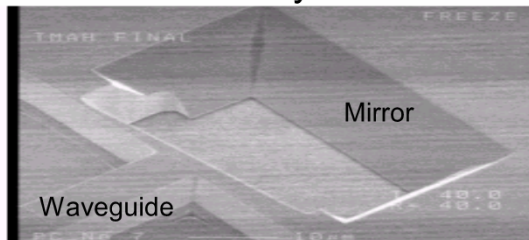
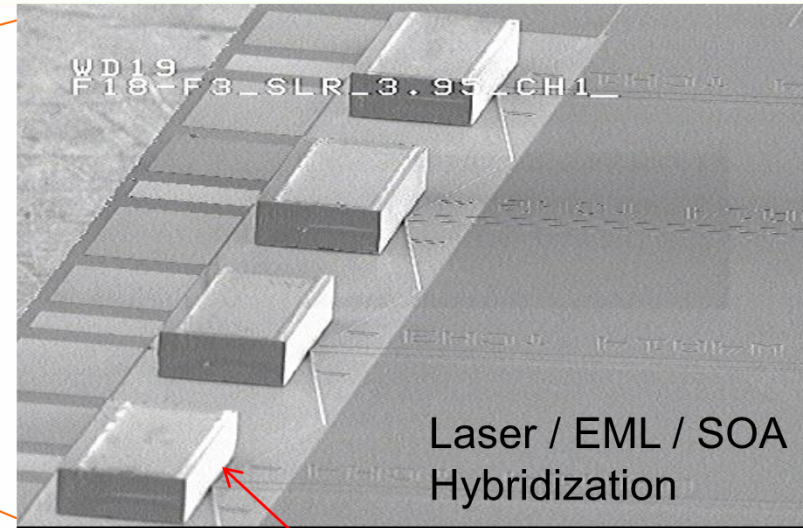
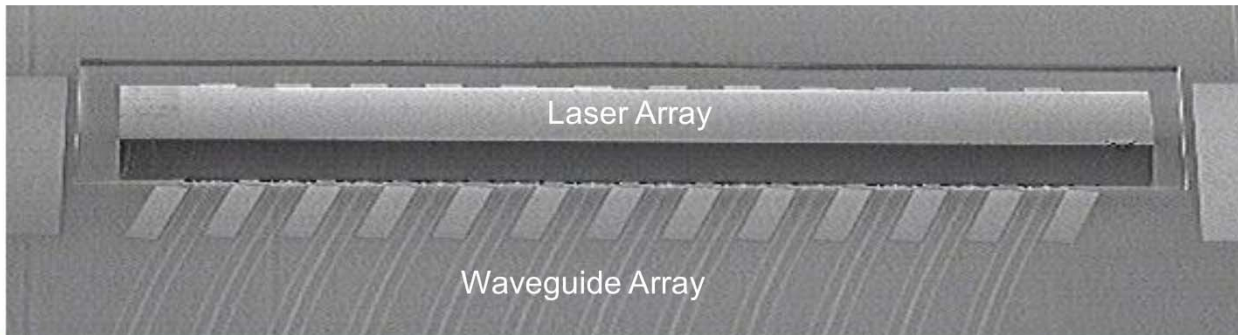


Photo-diode Hybridization

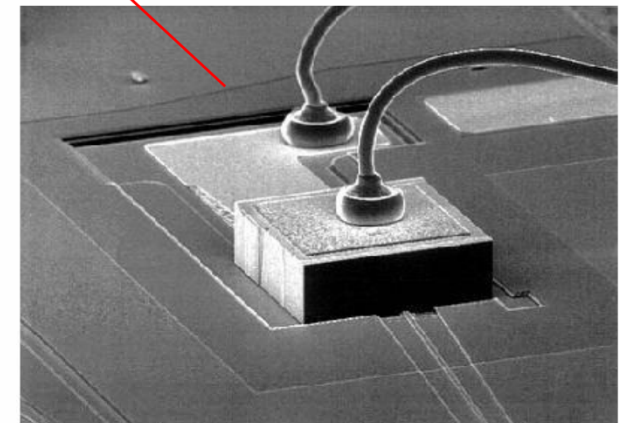


Mechanical features in Si interlock with III/V components for accurate positioning

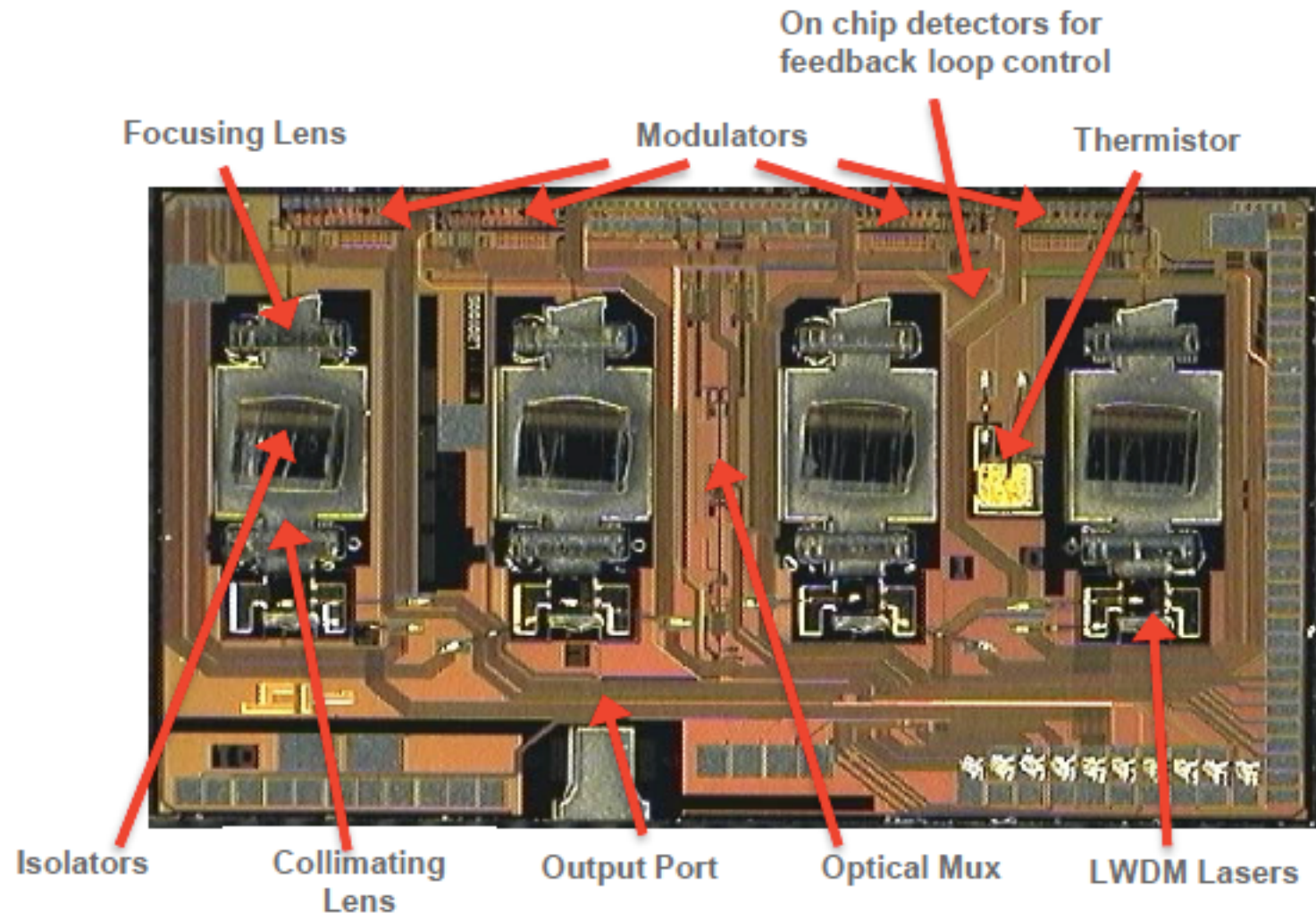


Laser / EML / SOA Hybridization

Coupling losses:
LD: 1.5-3dB
PD: 0.5-1dB
Back reflection:
<-45dB
3x3um Si WGs
used

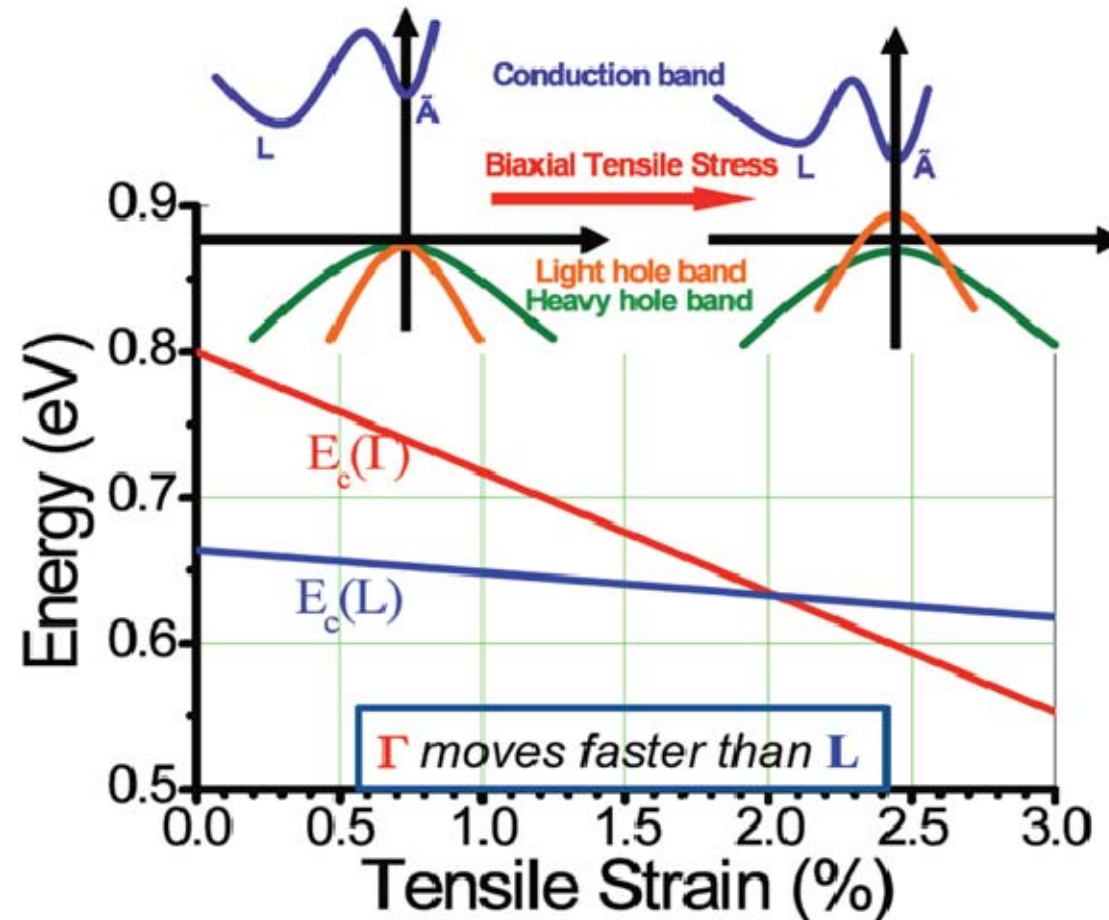


III/V chips (LD, EML, SOA, PD) can be flip chip attached on Si



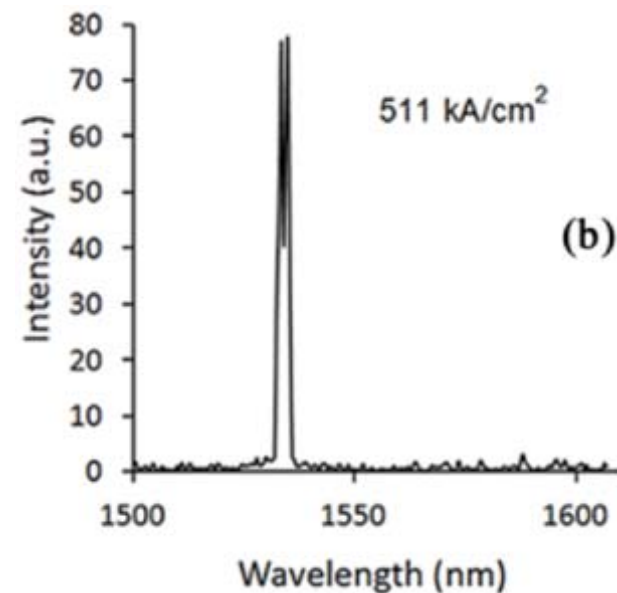
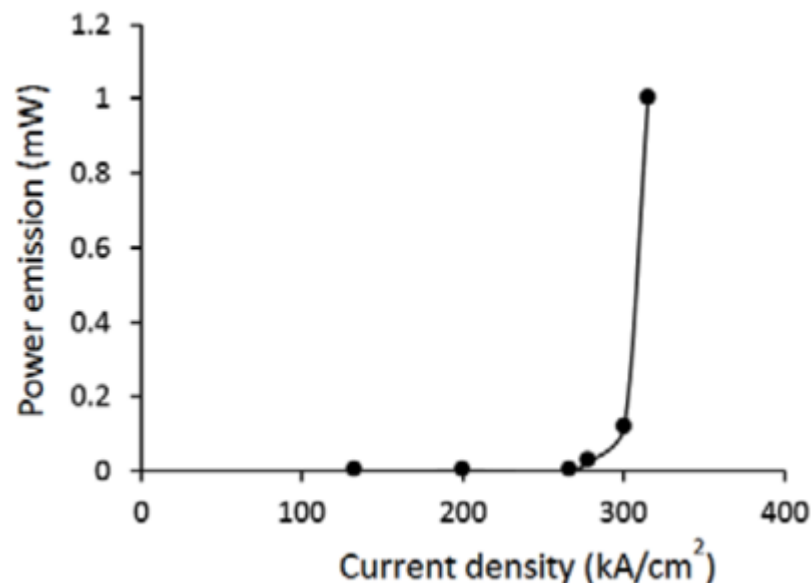
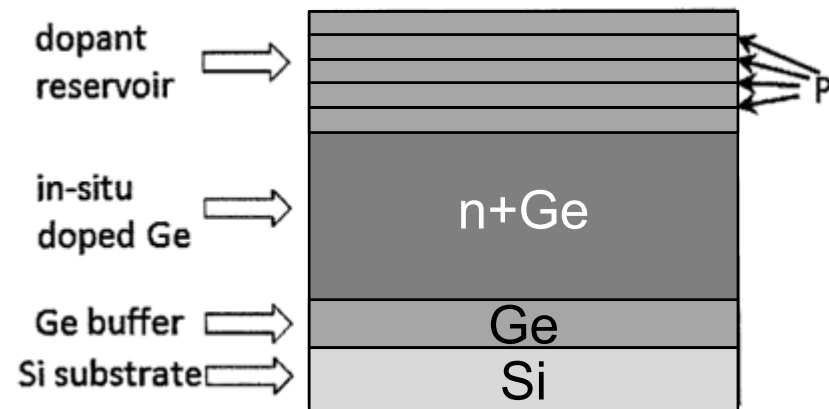
"OFC2014 : Packaging and Reliability of CMOS Photonics", Angelo Miele & David Piede (CISCO CPAK 100G LR4 design)

Ge-on-Si: in-plane tensile strain

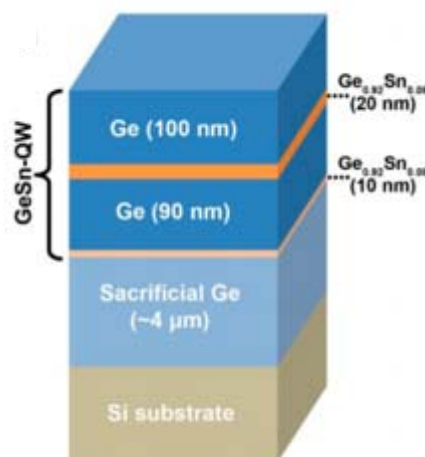
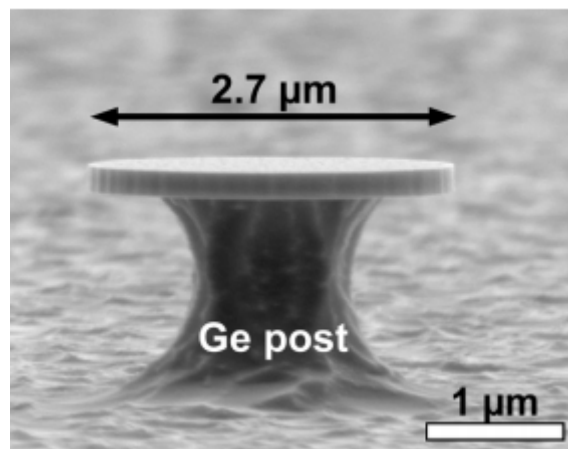


- Ge is pseudo-direct gap and compatible with CMOS.
- Tensile strain drives Ge towards direct gap behavior.

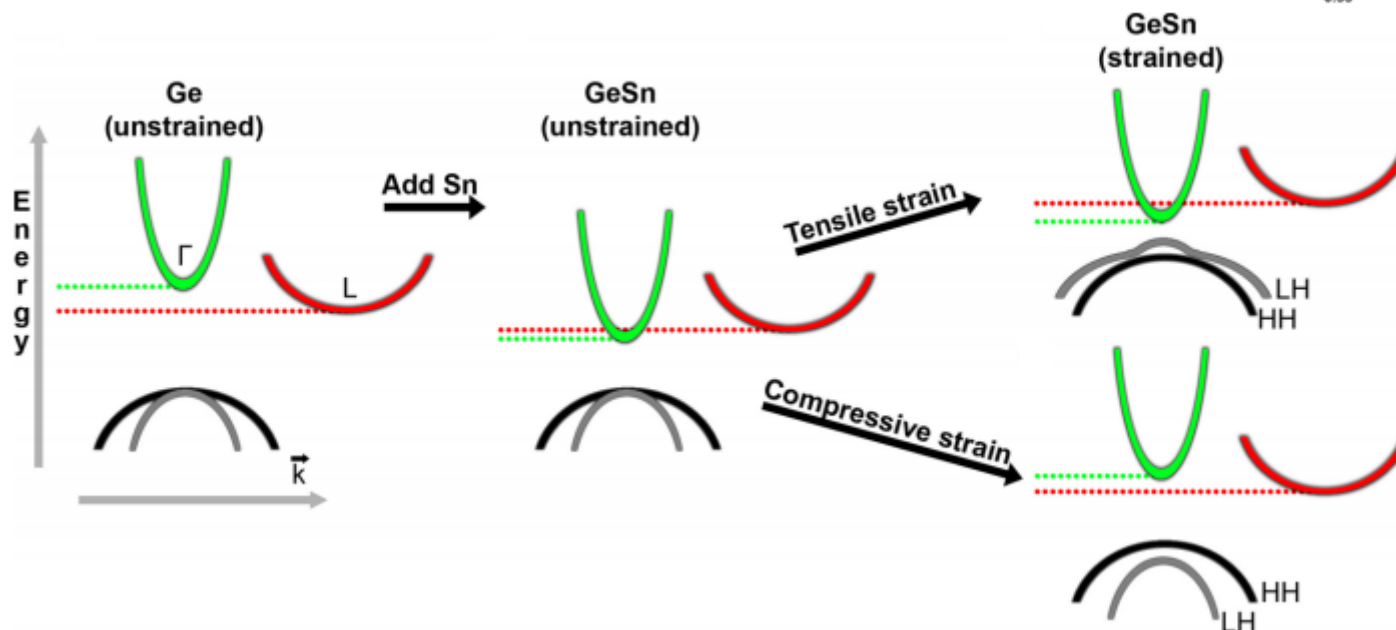
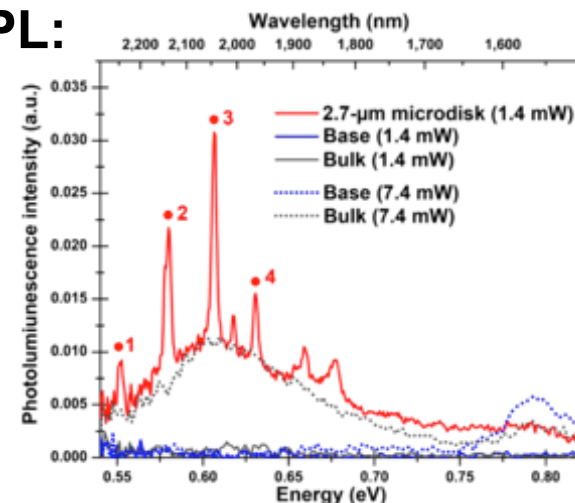
- Pulsed operation at 15 C
- Threshold 280 kA/cm²
- 1.7 V at threshold
- Threshold current: 0.6 A*
- Threshold power: 1 W*
- Output: 1 mW at 315 kA/cm²
- Efficiency $\sim 10^{-4}$



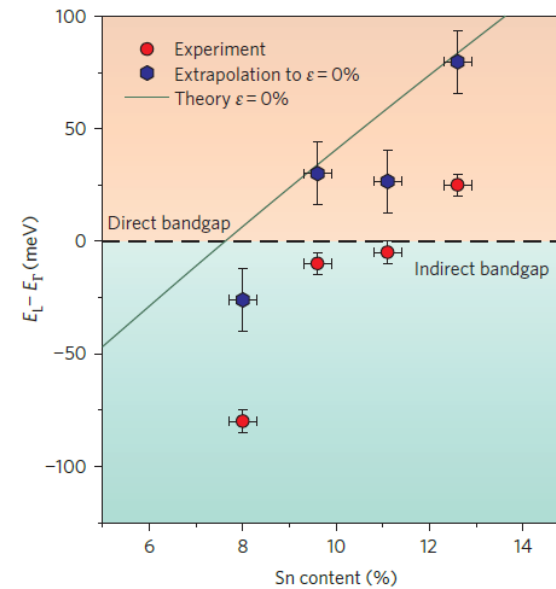
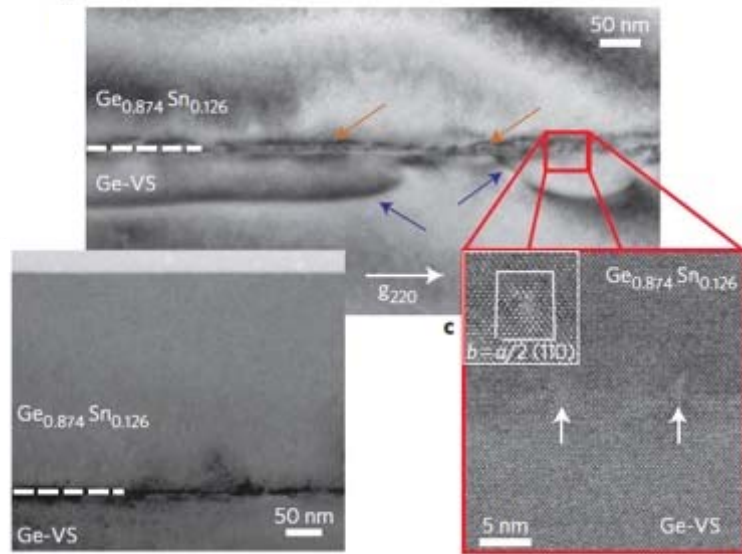
Pseudomorphic Ge/GeSn/Ge



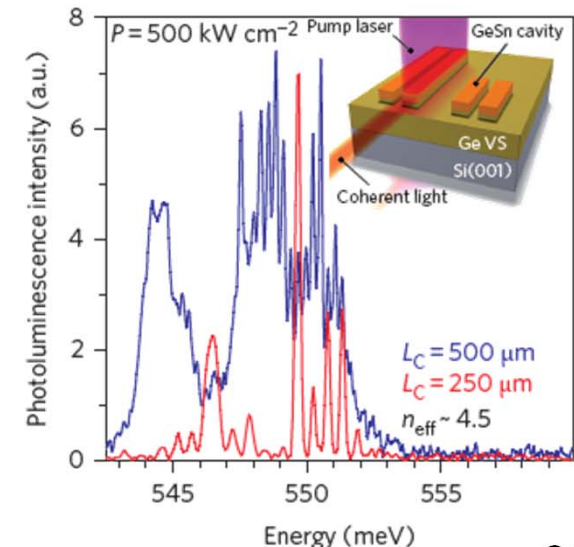
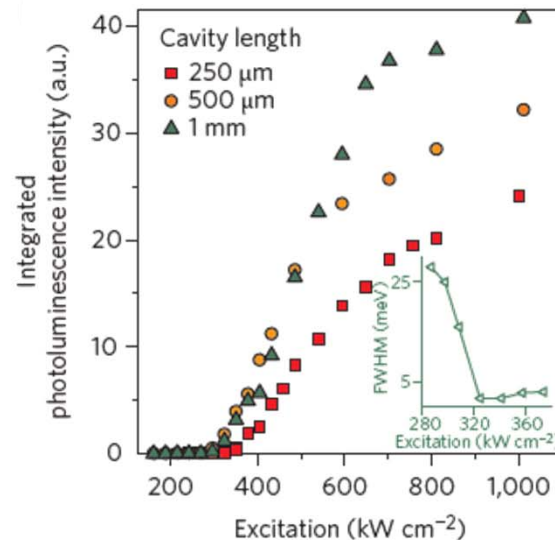
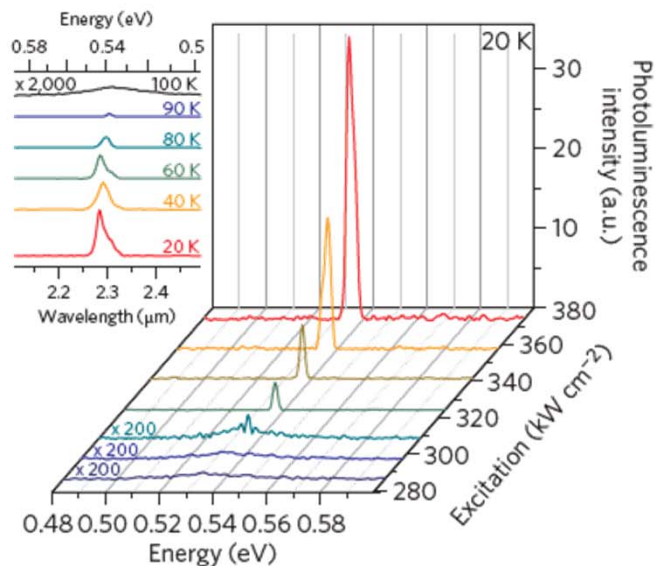
PL:



UCSB Lasing in direct-bandgap GeSn alloy grown on Si



Optical pump

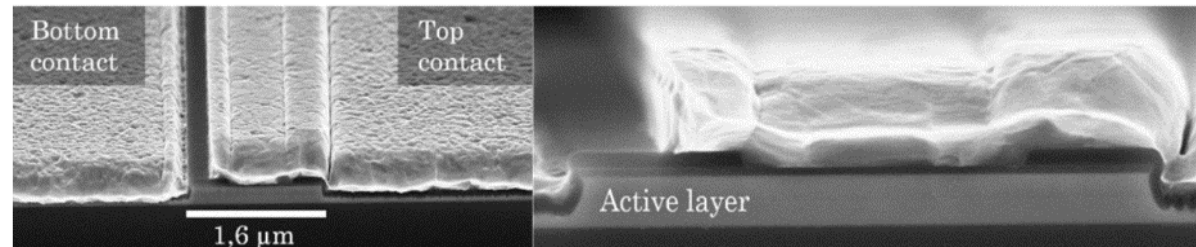
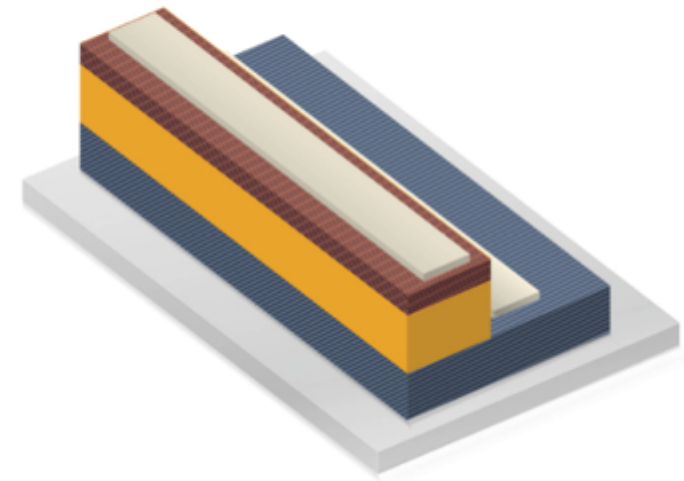
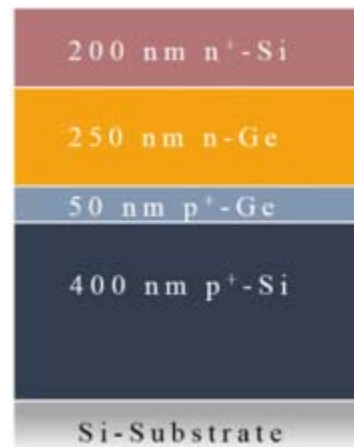
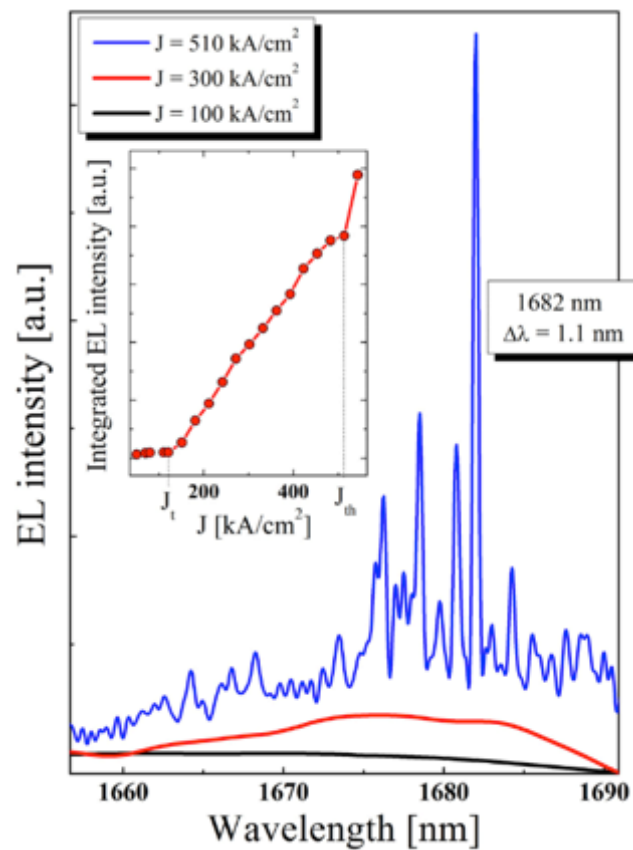


S. Wirths et al., Nat. Photon. 9, 88 (2015).

Electrically pumped lasing from Ge Fabry-Perot resonators on Si

Al contacts
 Top layer
 Buried layer
 Substrate

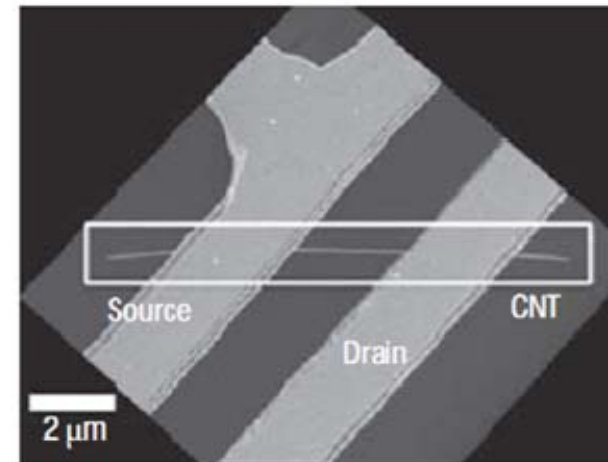
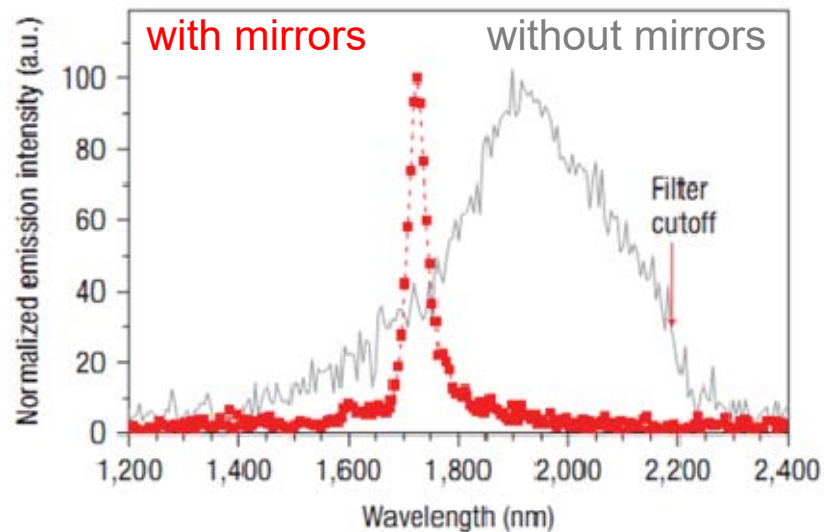
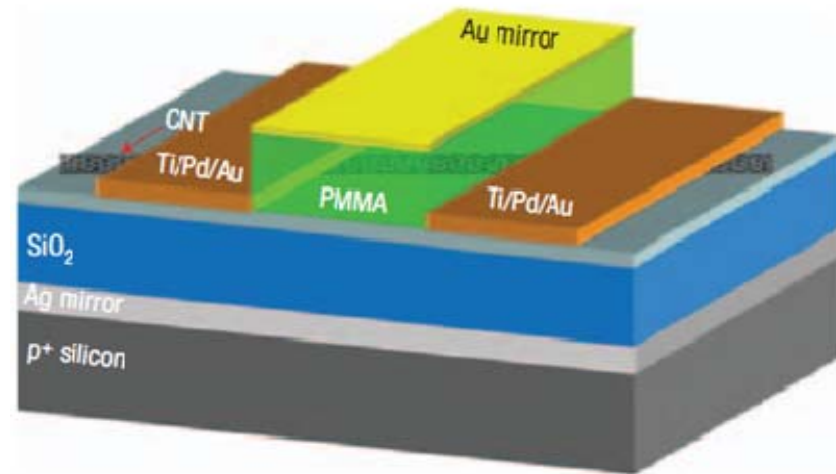
Optical window
 Optical active layer



G. Sun, HH. Cheng, J. Menendez, J. B. Khurgin, and R. A. Soref

The figure is a plot of Energy [eV] versus Growth Dimension [Å]. The y-axis ranges from 0.00 to 0.25 eV, and the x-axis ranges from 0 to 800 Å. The plot is divided into two main regions: 'Injector' (from 0 to approximately 350 Å) and 'Active' (from approximately 350 to 550 Å). Several energy bands are shown, with three specific bands labeled 1, 2, and 3. Band 1 is the lowest, followed by band 2, and then band 3. The bands are shown as a series of steps, indicating discrete energy levels. The growth dimension is marked with values 0, 200, 400, 600, and 800 Å. The injector region is marked with values 50, 52, 54, 56, 60, 10, and 30. The active region is marked with values 60, 60, 50, and 30. A red arrow points down to band 3, and a blue arrow points up to band 1.

- Current injection of nanotube transistor;
- Generally: CNT EL spectrum broad, non-directional;
- with $\lambda/2$ microcavity $\rightarrow$ narrow ($\sim 40\text{nm}$) and directional spectrum @ $1.75\text{ }\mu\text{m}$.

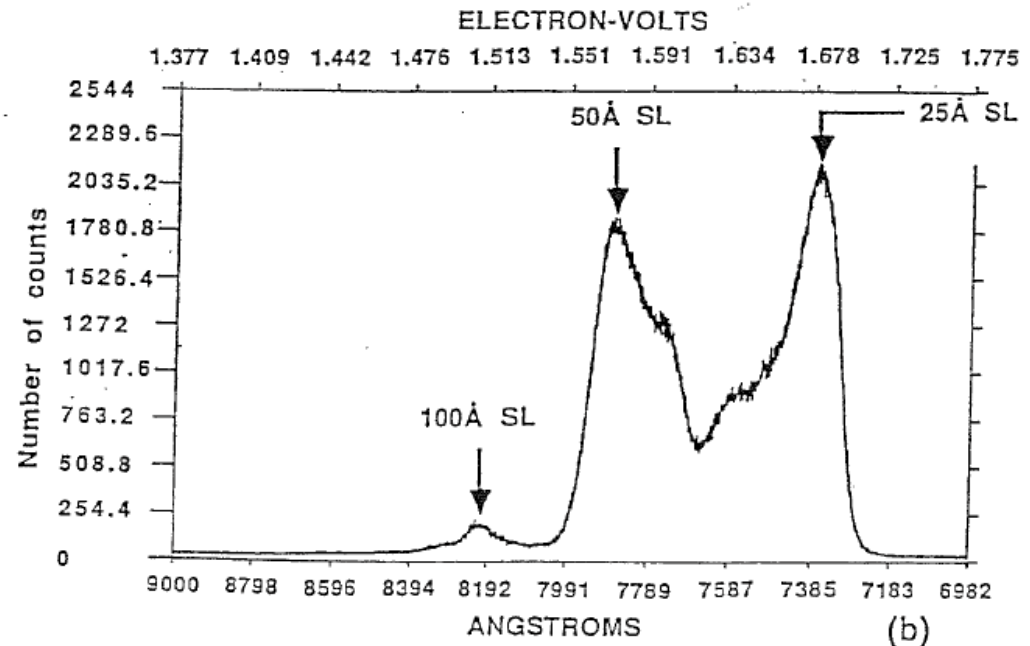
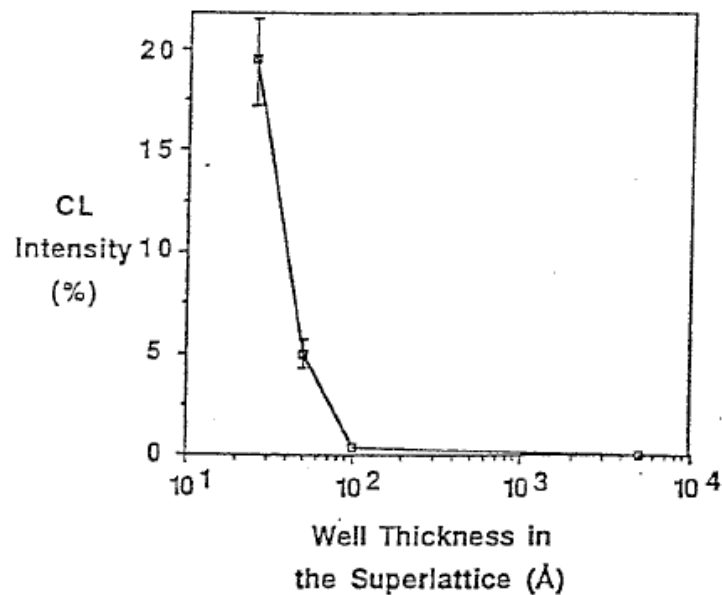


Epitaxial III-V Quantum Wells on Si

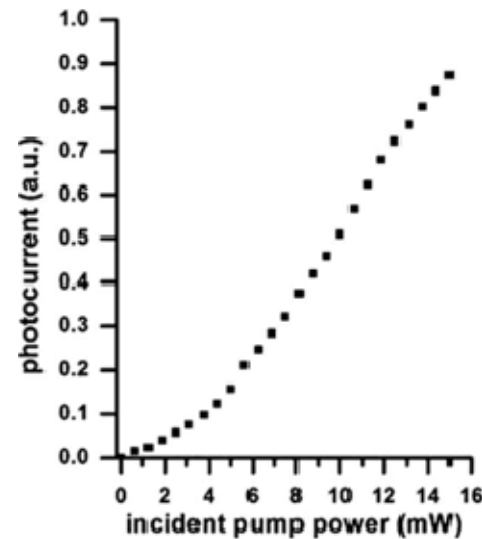
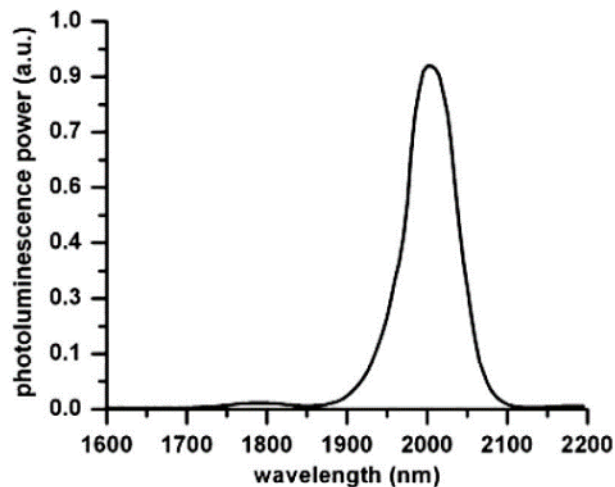
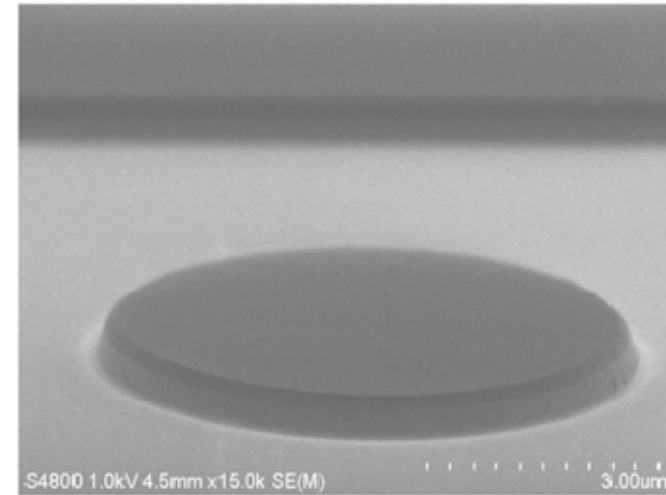
Quantum well: historically poor emission and poor lifetime. Two examples:

- Van der Ziel, et al. "Degradation of GaAs lasers..." APL (1987): 89-91. **8 sec lifetime**
- Liu, Petroff, Kroemer JAP 64 (1988):

GaAs/AlAs Superlattices on Silicon



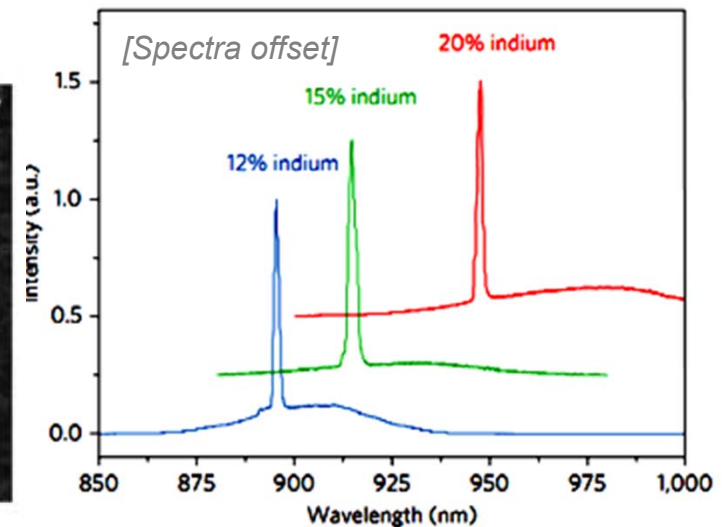
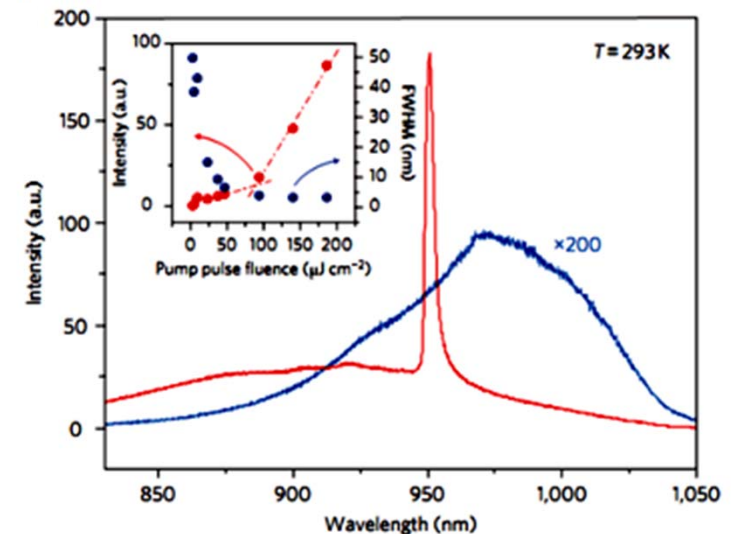
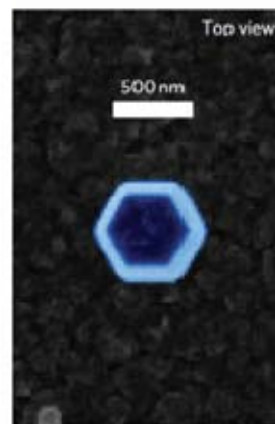
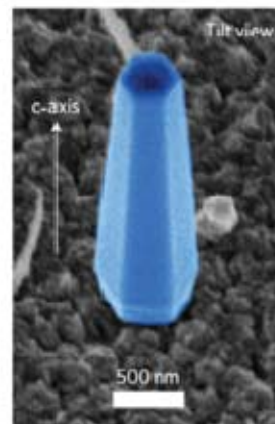
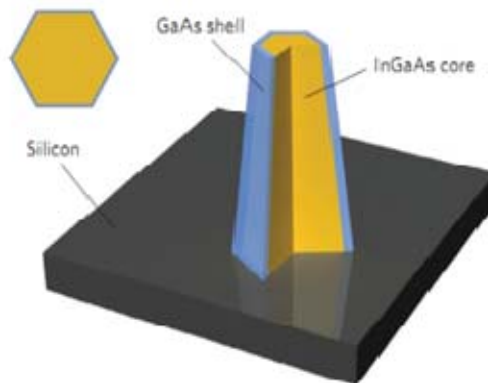
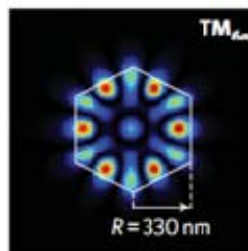
- III-Sb monolithically grown on silicon substrate
 - interfacial misfit array to relieve lattice mismatch;
- 5- μ m diameter disk
- RT lasing @ 2 μ m;
- optical pumping @850 nm.



Nanolasers grown on silicon

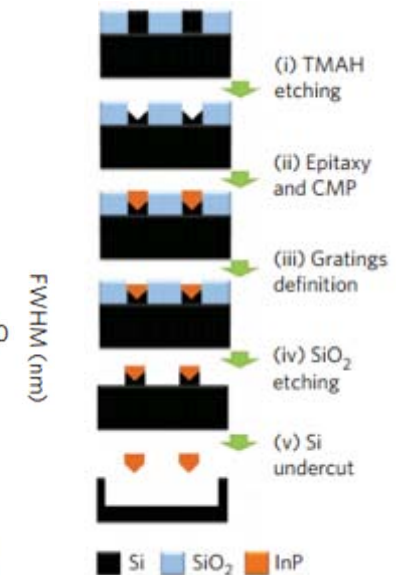
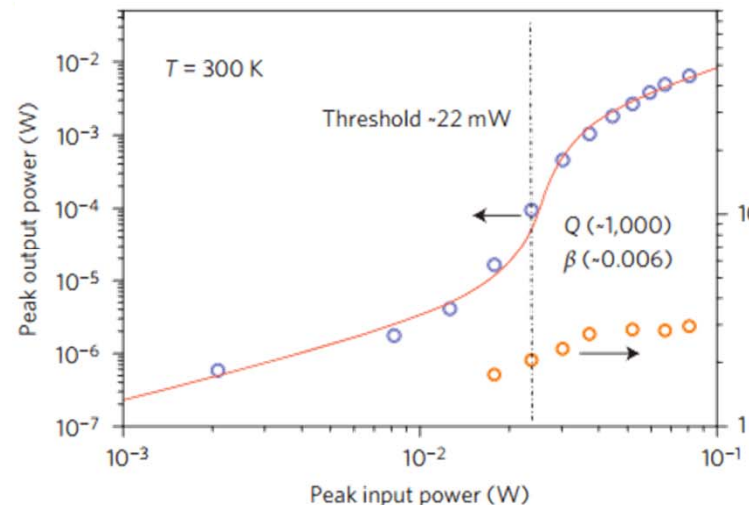
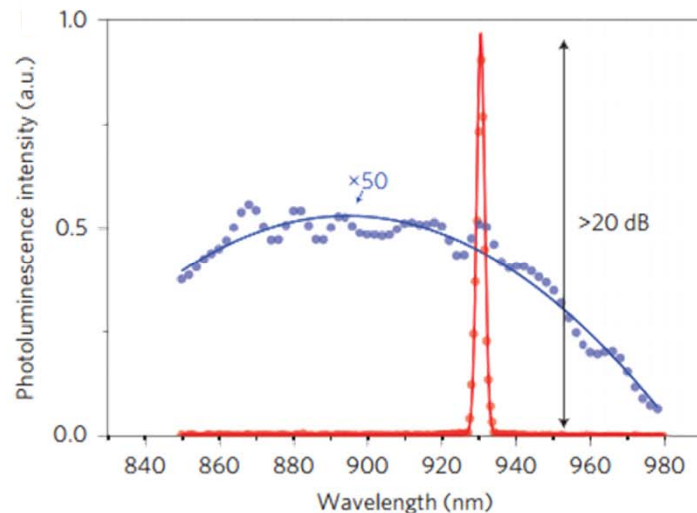
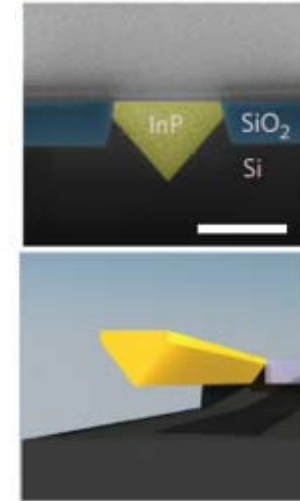
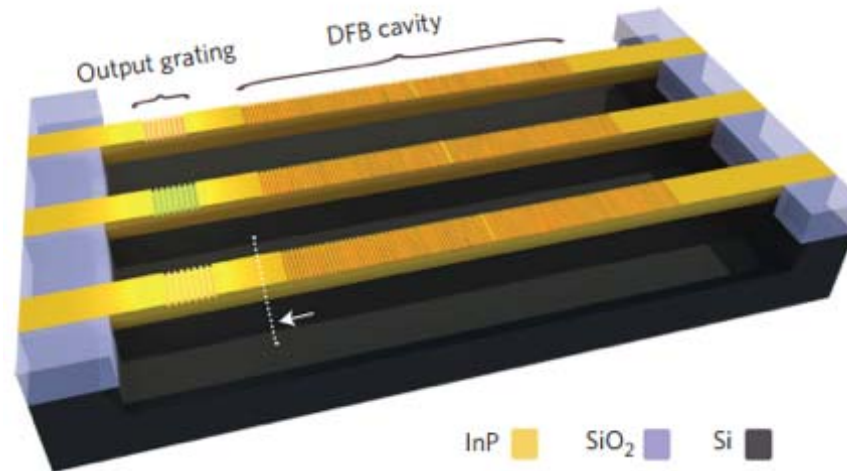
C. Chang Hasnain (UC Berkeley)

- III–V nanolaser grown on silicon;
- room-temperature operation;
- subwavelength volume;
- helically propagating cavity modes.



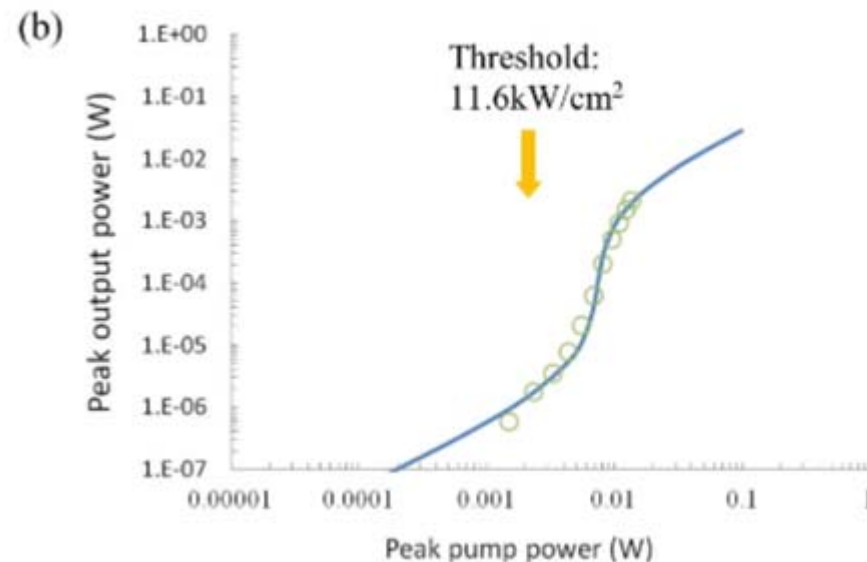
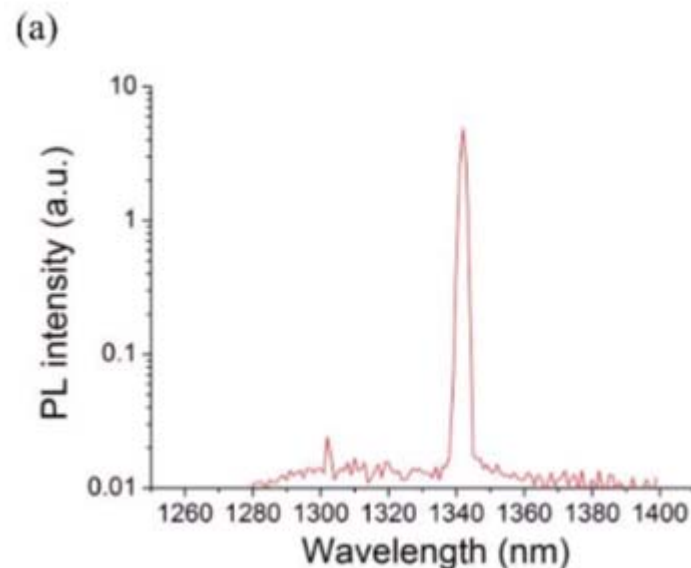
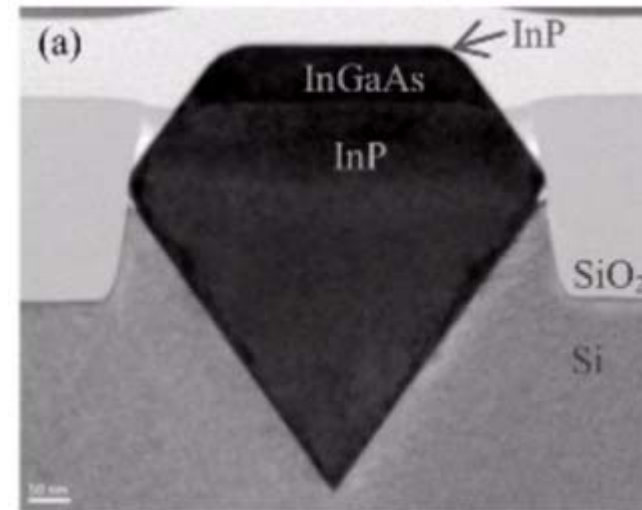
UCSB Room-temperature InP distributed feedback laser array directly grown on silicon

- Optically pumped
- Threading dislocations and anti-phase boundaries suppressed to <20 nm thick layer



UCSB RT InGaAs/InP distributed feedback laser array directly grown on silicon at 1.3 μ m

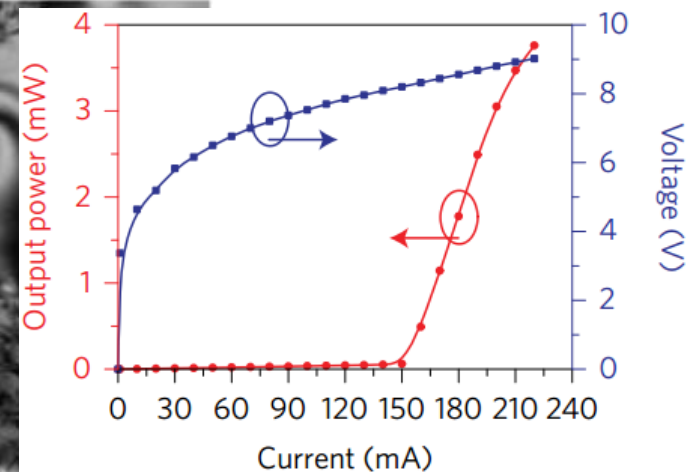
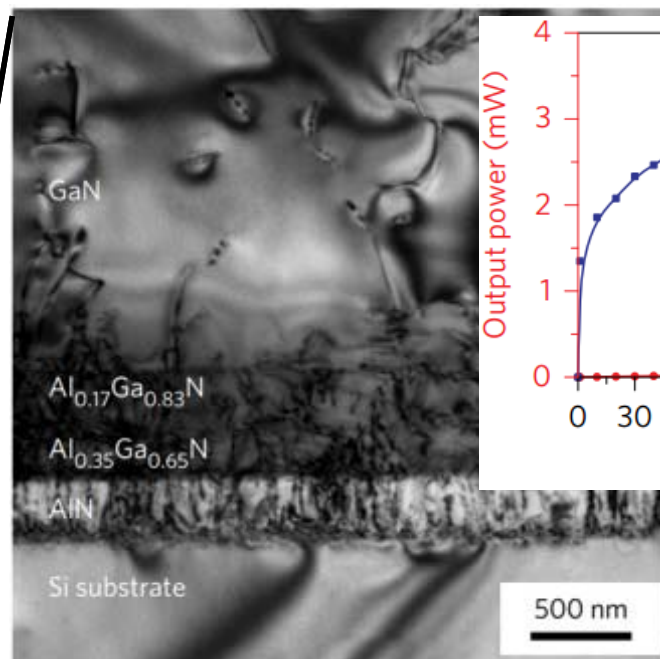
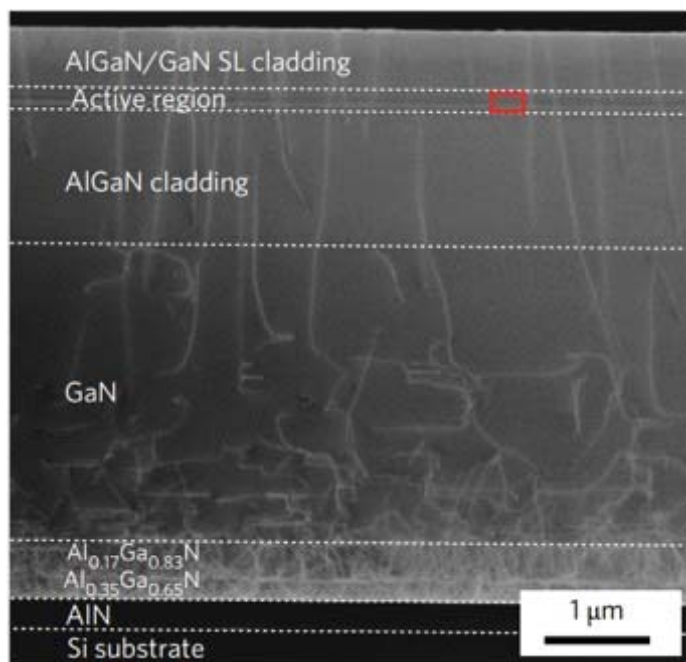
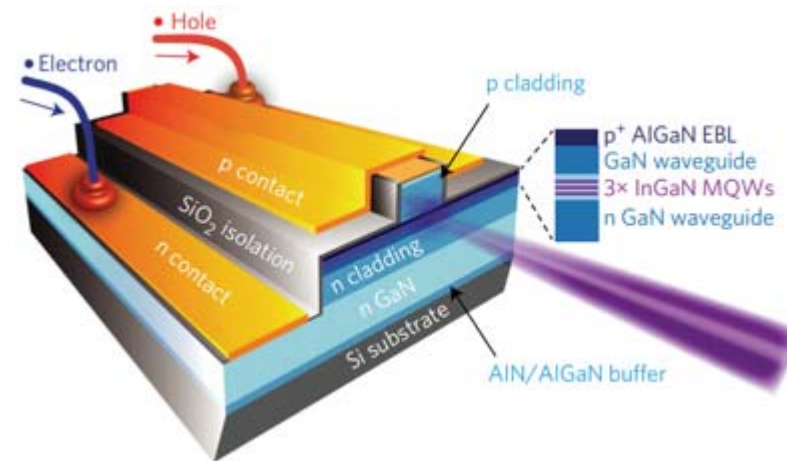
- Prior technique further explored
- CMP $\rightarrow$ MOCVD overgrowth of InGaAs alloy



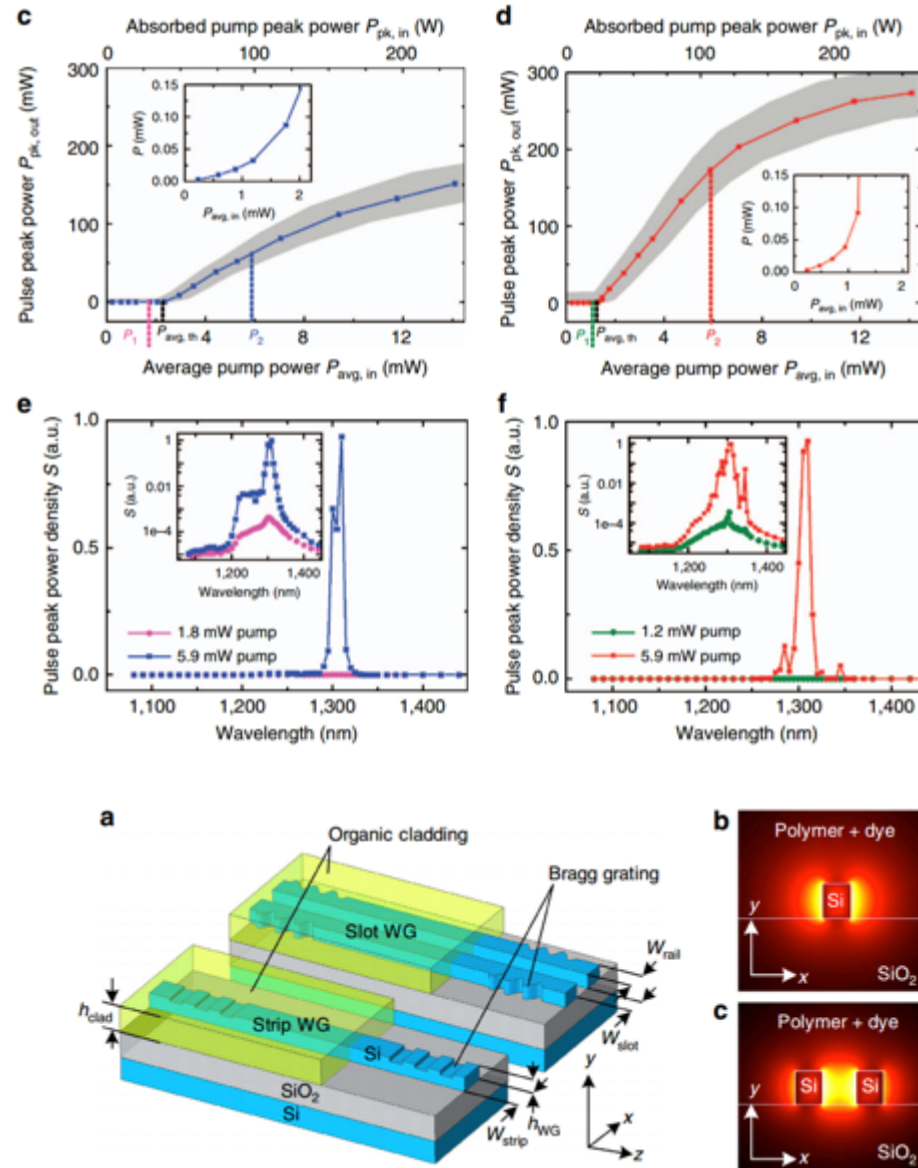
Z. Wang *et al.* CLEO (2016).

Room-temperature continuous-wave electrically injected InGaN-based laser directly grown on Si

- InGaN MQWs
- Key advance is using $\text{Al}_{0.35}\text{Ga}_{0.65}\text{N}/\text{AlN}$, then $\text{GaN}/\text{Al}_{0.17}\text{Ga}_{0.83}\text{N}$ to facilitate threading dislocation bending

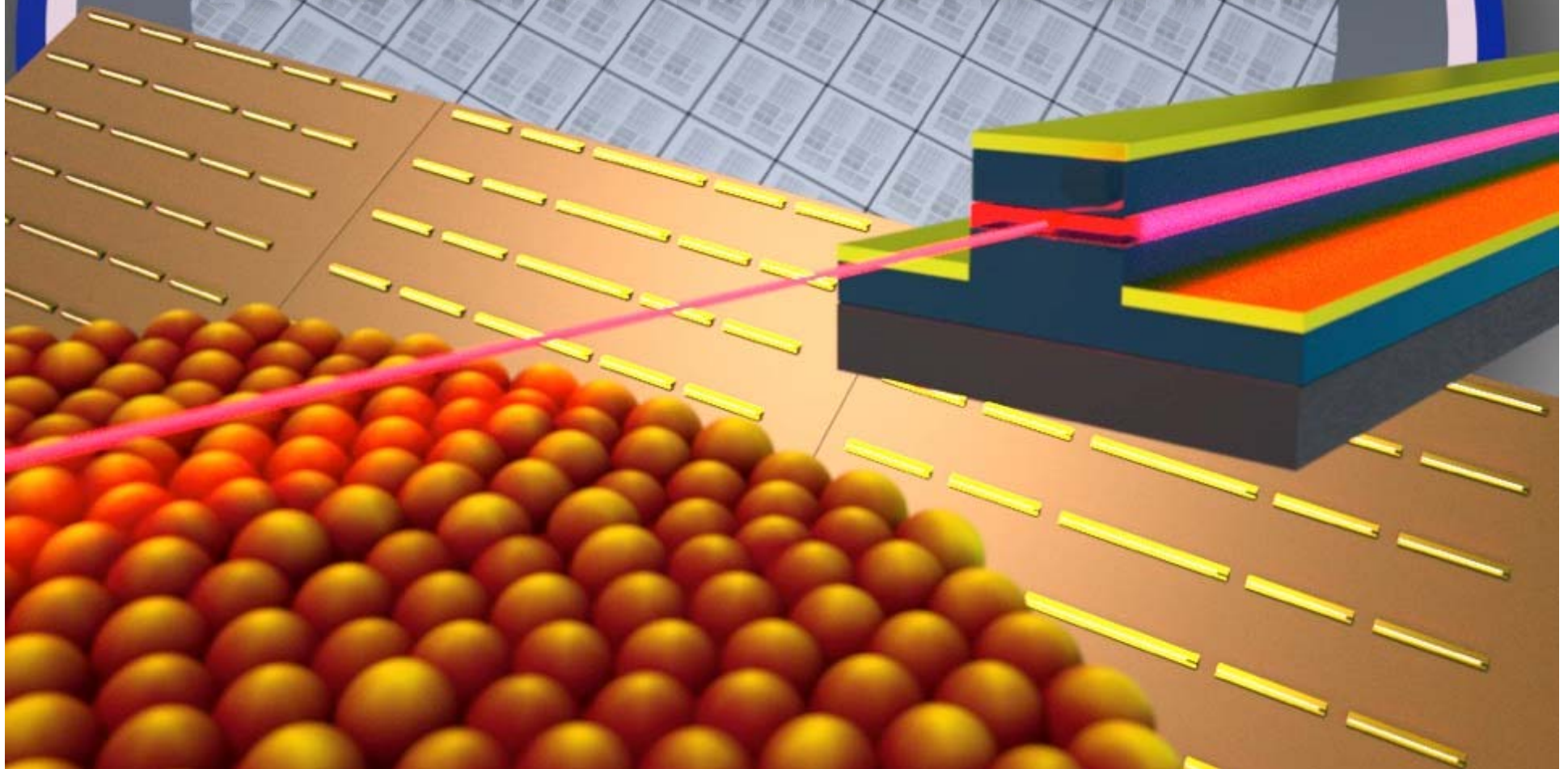


- Si slot and strip waveguides coated in IR26 doped PMMA
- Optical pumping achieves lasing at 1310 nm
- Threshold for strip, slot = 2.3, 1.3 mW

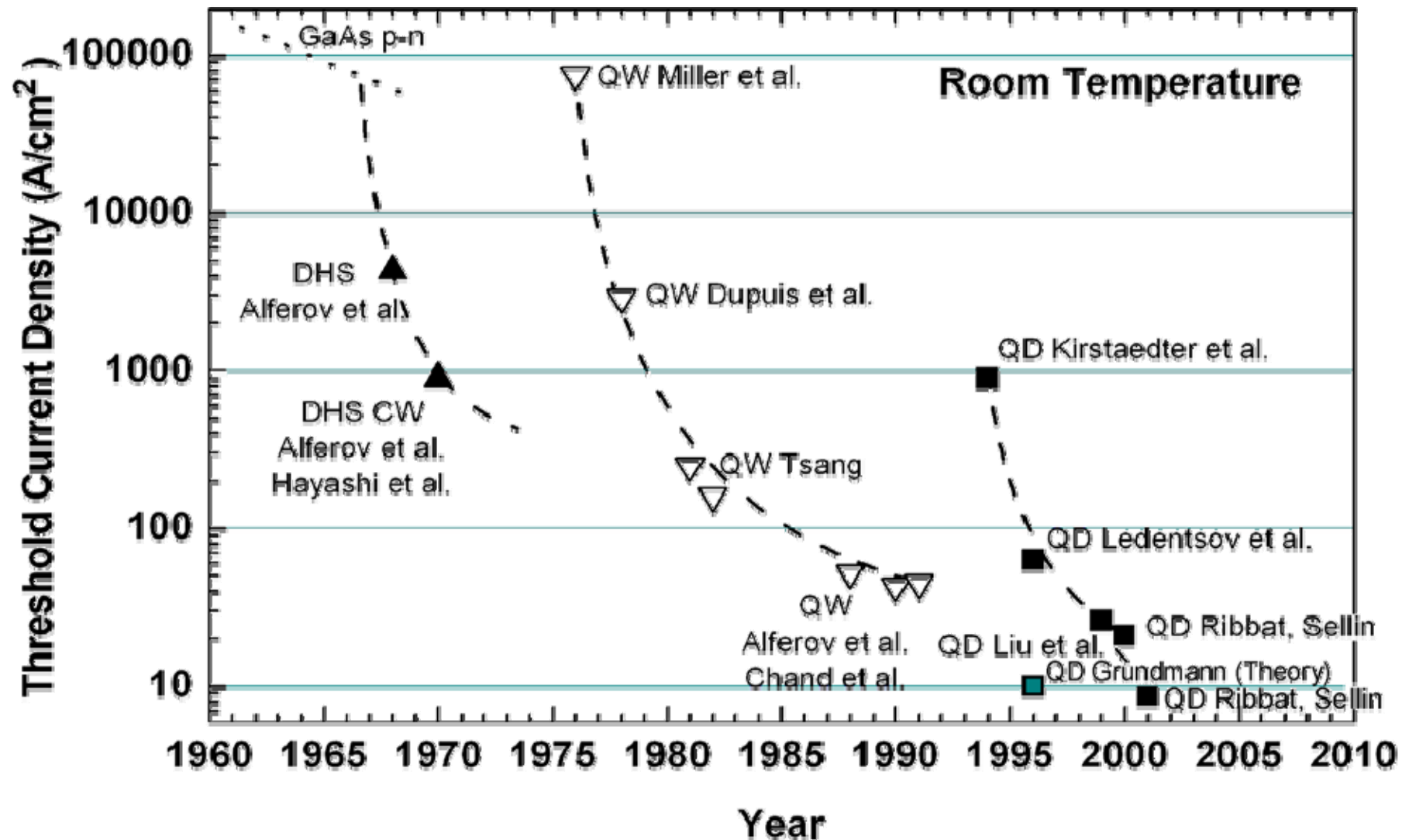


D. Korn *et al.* Nat. Commun. 1(2016).

QUANTUM DOT LASERS EPITAXIALLY GROWN ON SILICON



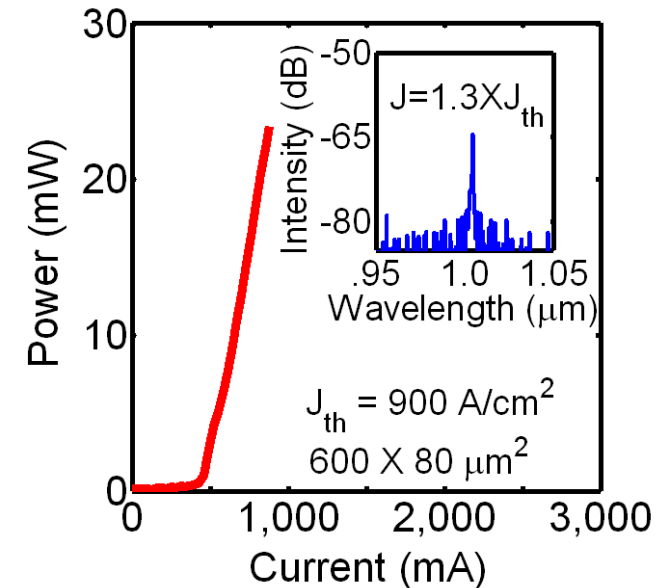
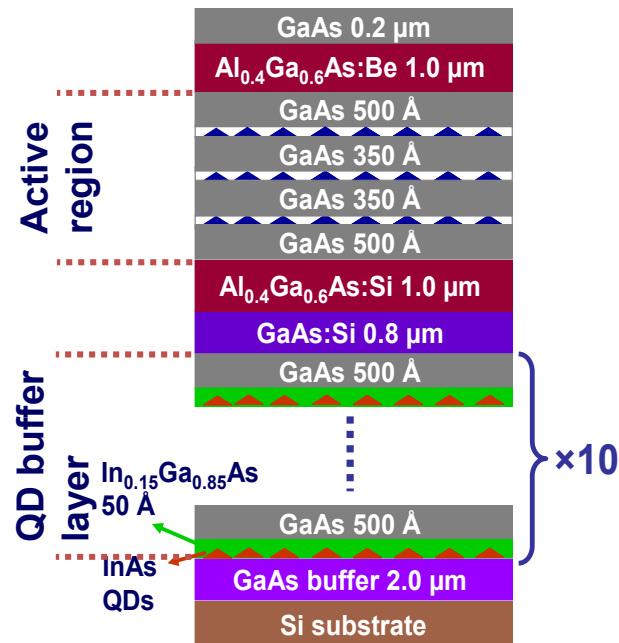
Threshold Current Densities of Semiconductor Lasers



QD-lasers for lower thresholds

Survey of Quantum Dot Lasers on Silicon

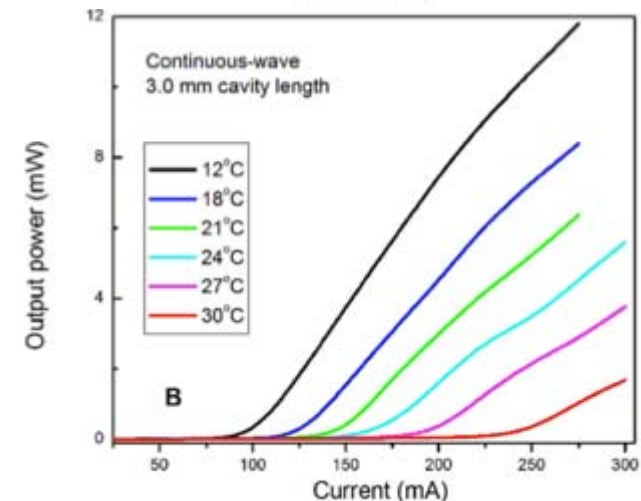
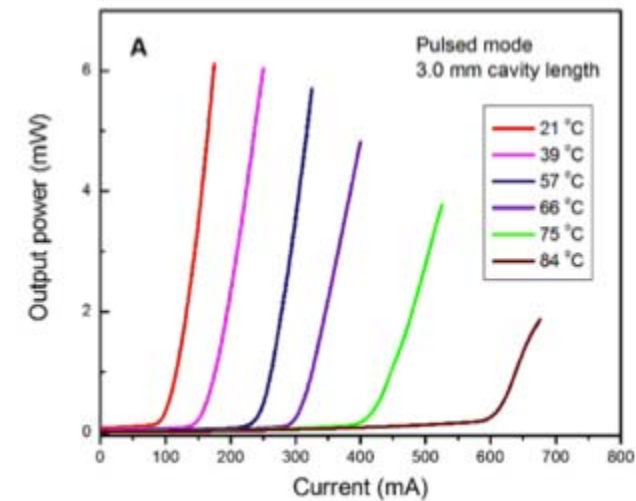
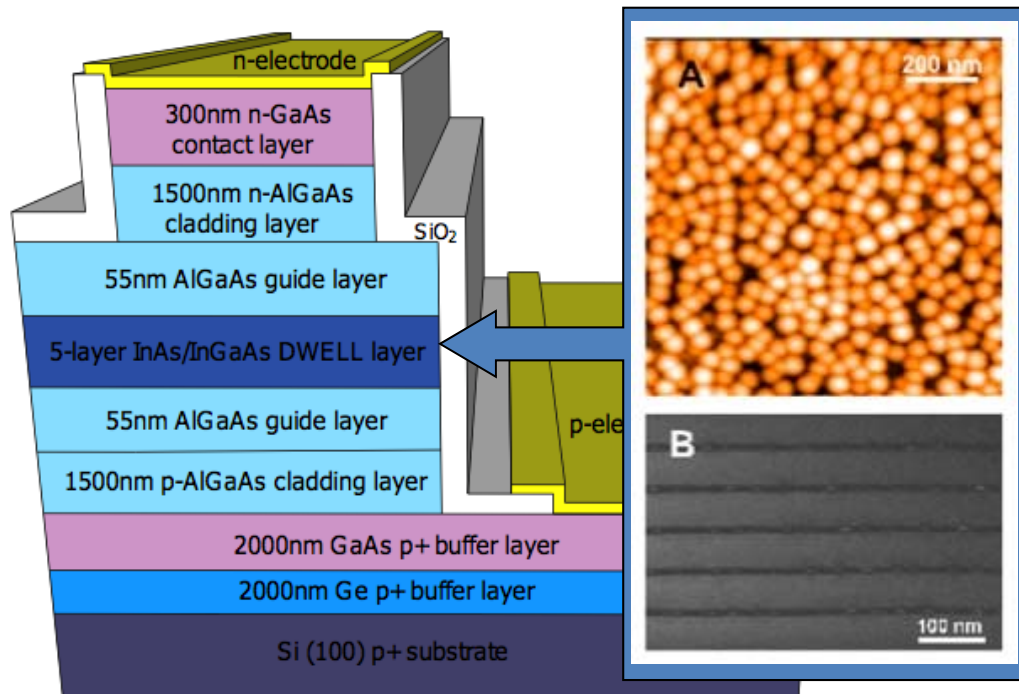
- 1999 – First laser operation with $\text{In}_{0.4}\text{Ga}_{0.6}\text{As}$ QDs @ 1 μm . Pulsed at 80 K (Bhattacharya, University of Michigan)
- 2005 – RT Pulsed operation with $\text{In}_{0.5}\text{Ga}_{0.5}\text{As}$ QDs @ 1 μm (Bhattacharya, University of Michigan)



- **(001)-oriented Si substrates misoriented 4° towards [111] are used to eliminate the formation of antiphase domains and stacking faults at the GaAs/Si interface.**

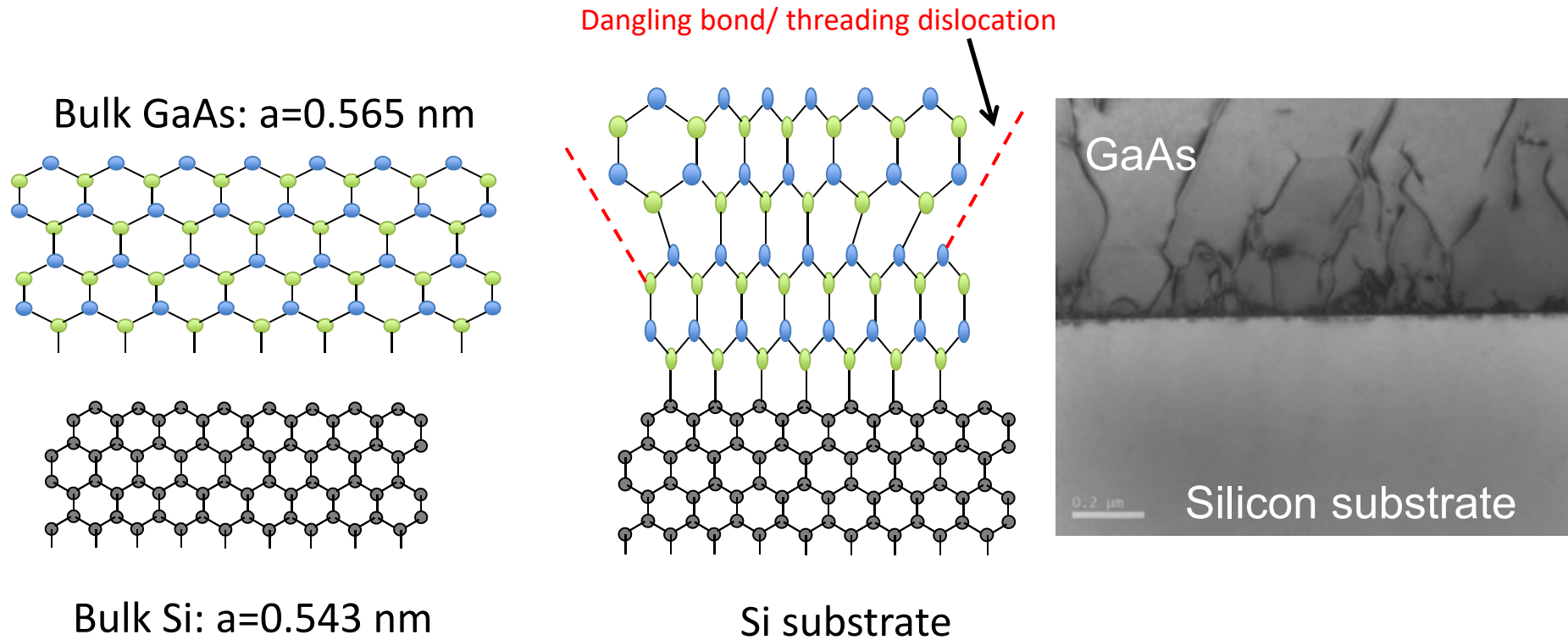
Survey of Quantum Dot Lasers on Silicon

- 1999 – First laser operation with $\text{In}_{0.4}\text{Ga}_{0.6}\text{As}$ QDs @ 1 μm . Pulsed at 80 K (Michigan)
- 2005 – RT Pulsed operation with $\text{In}_{0.5}\text{Ga}_{0.5}\text{As}$ QDs @ 1 μm (Michigan)
- **2011 – First RT CW operation with InAs QDs @ 1.3 μm (Huiyun Liu's group at UCL)**
- Thresholds:
 - 63.4 A/cm² pulsed (44.3 mA for 3.5mm x 20 μm)
 - 163 A/cm² CW (114 mA for 3.5mm x 20 μm)
- CW lasing up to 30 °C



(A. Lee et al. Opt Express, **20**, 2012)

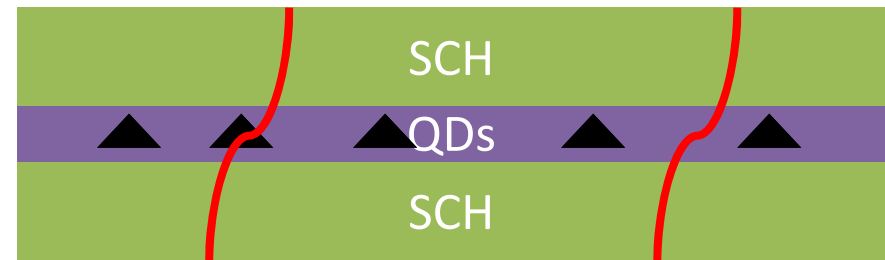
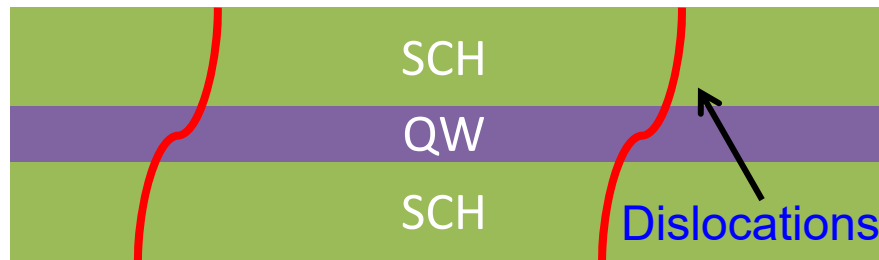
- Polarity, lattice & thermal expansion mismatch between silicon and III-Vs result in high dislocation densities
 - High thresholds (or no lasing), and poor reliability for QW lasers.



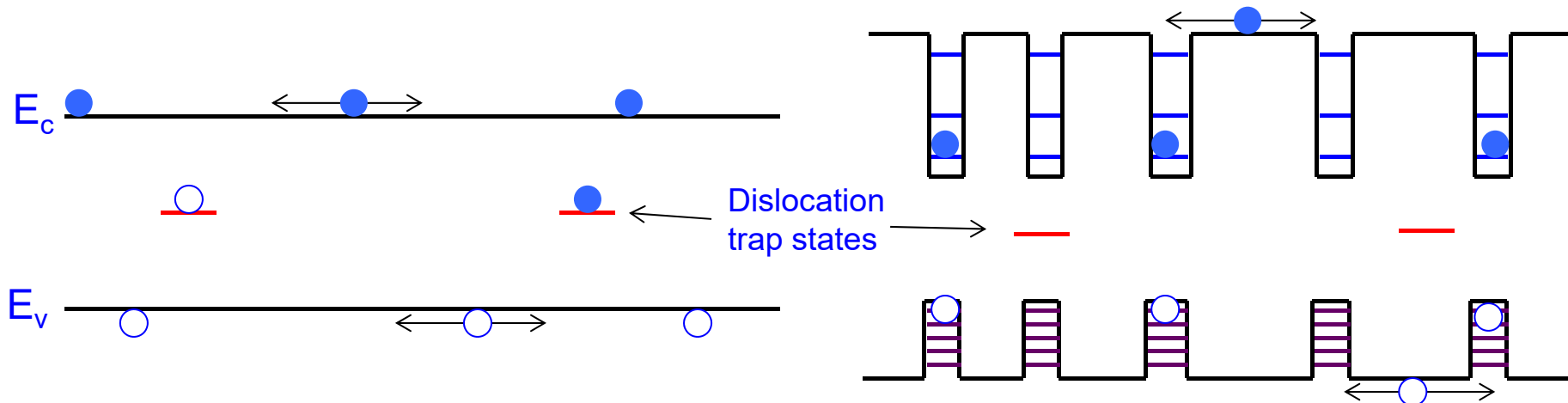
Solution: Use Quantum Dots

1991 – “Semiconductor Structure for Optoelectronic Components with Inclusions”
(Jean Gerard & Claude Weisbuch), U.S. Patent No. 5,075,742

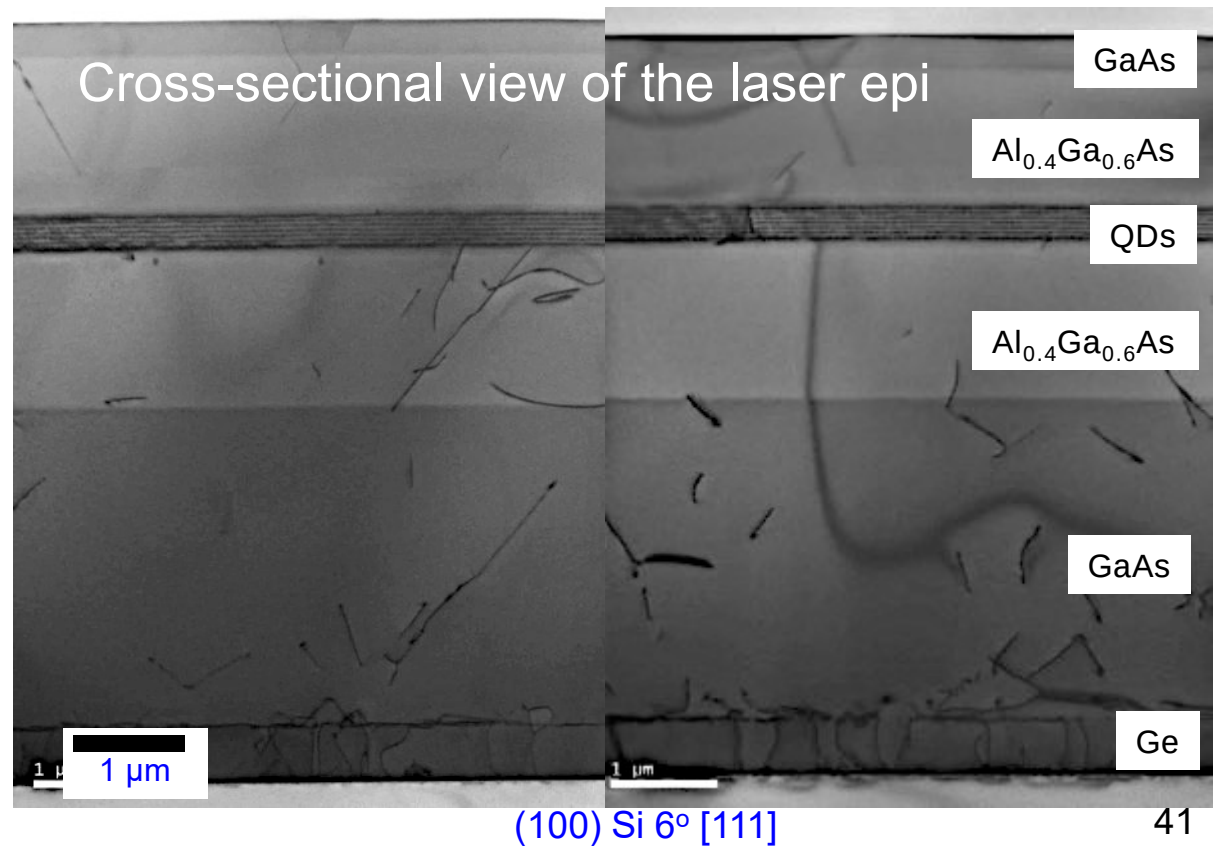
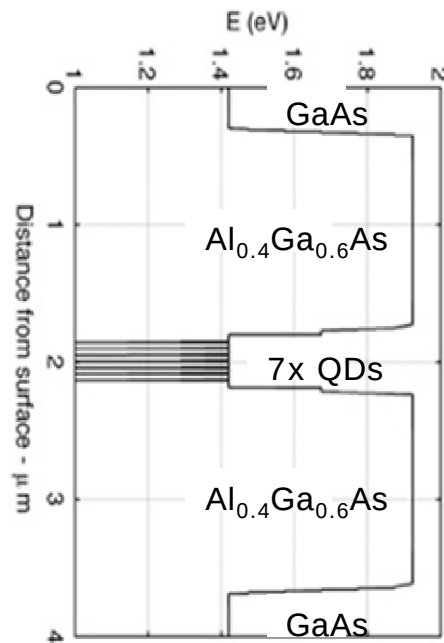
- 3D confinement provided by quantum dots prevents carriers from migrating to dislocations.



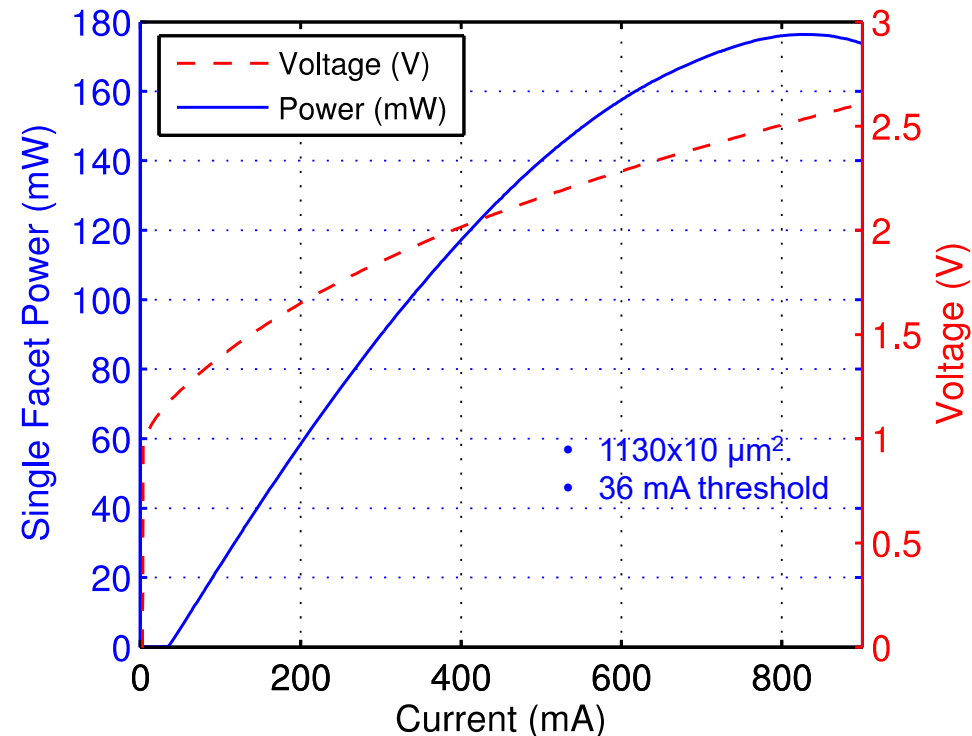
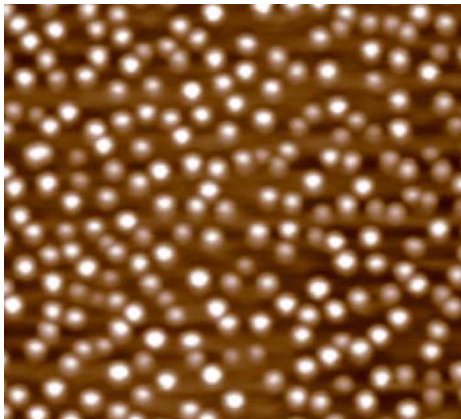
In-plane band diagram:



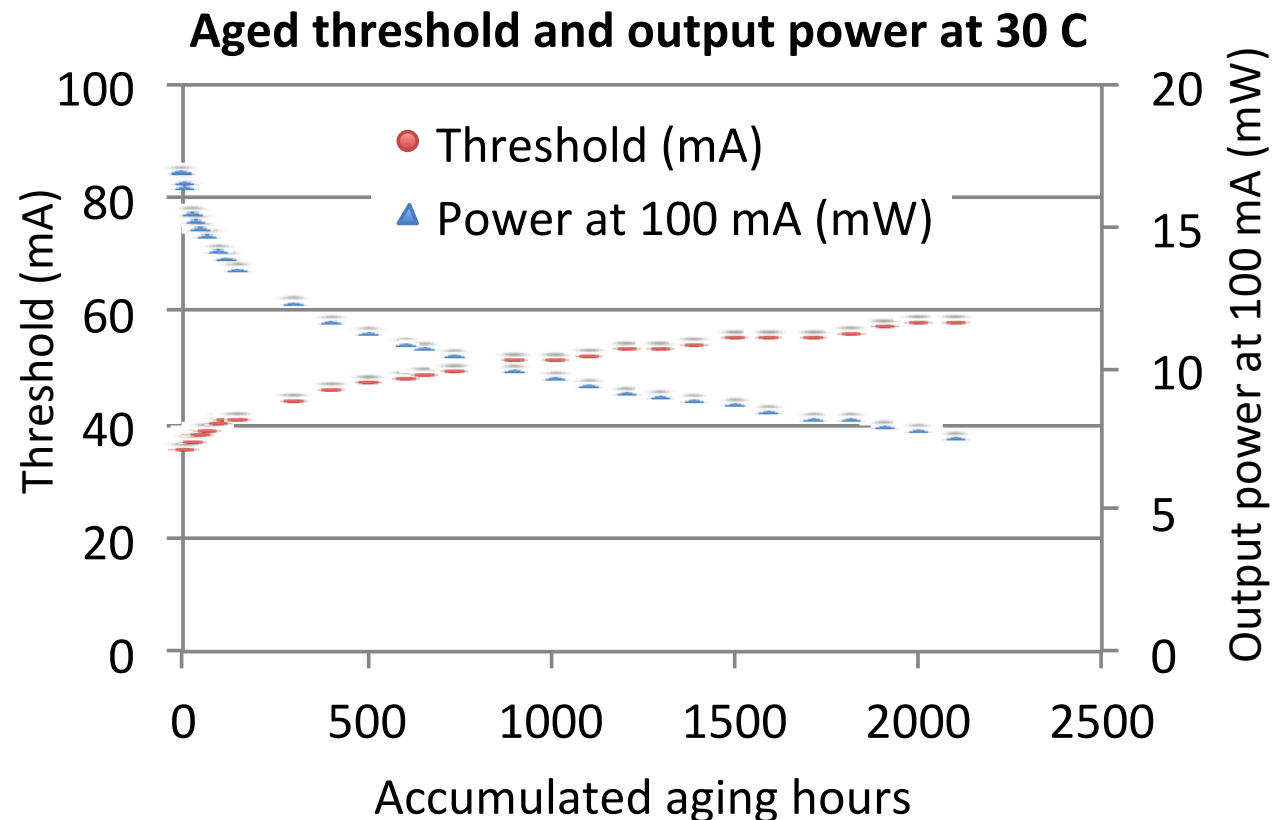
- TEM images of unprocessed laser material
- $>10^8 \text{ cm}^{-2}$ dislocation density in the QD active region



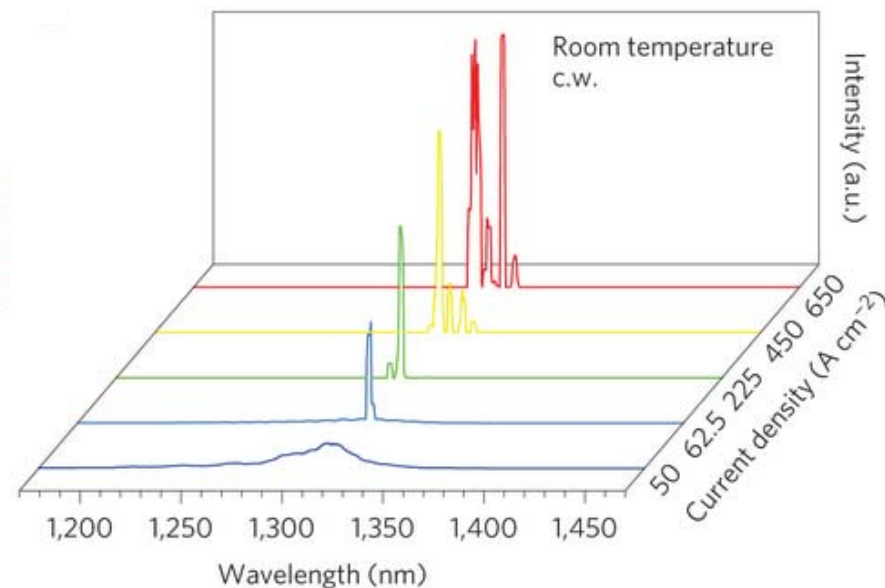
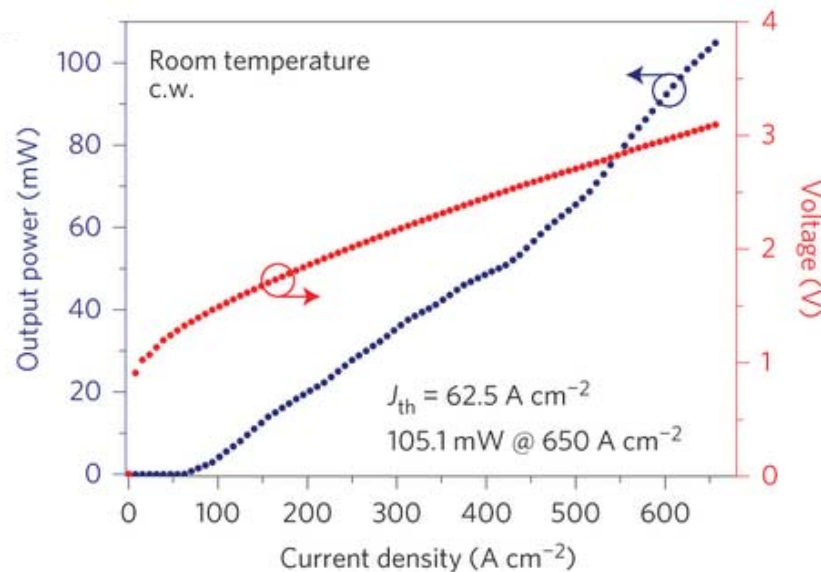
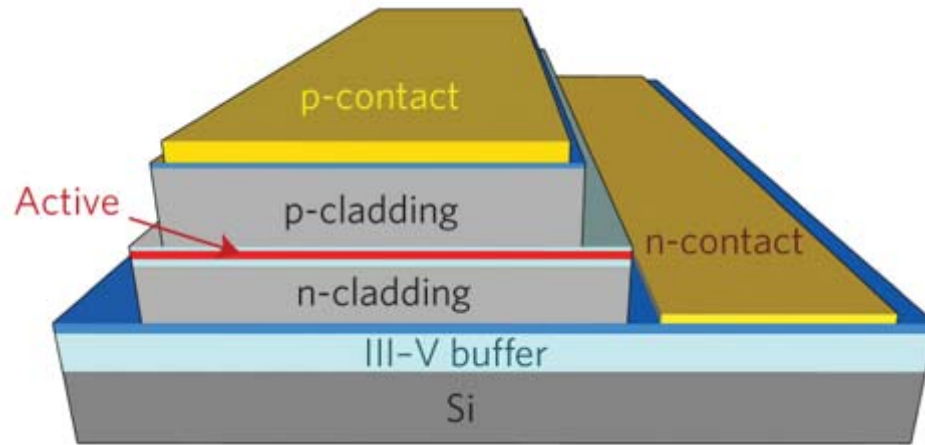
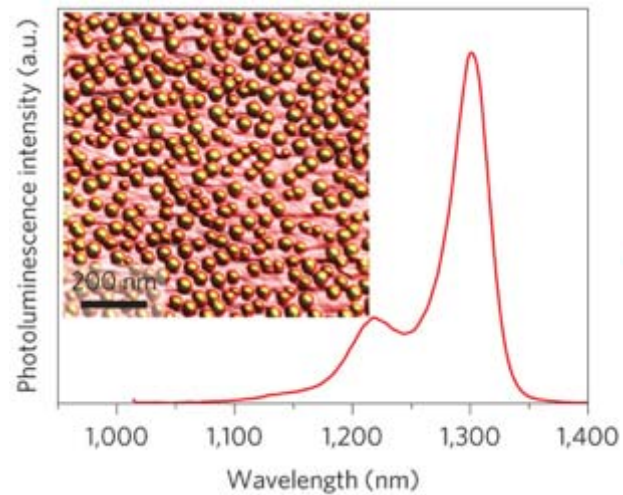
- Stranski Krastanov Quantum Dot Growth
- Low CW threshold (150 A/cm^2)
- CW powers over 100 mW routinely achieved.
- Nearly **180 mW** maximum CW single side output power at 20°C
- 33% differential efficiency and 18% WPE (at 150 mA)
- CW lasing to 119 C



- Lattice mismatch causes dislocations, which have limited quantum well laser reliability on Si.
- Over **2100 hours** of continuous operation
- **>26x** improvement over best reported lifetime for GaAs laser on Si
- Not yet adequate for real applications



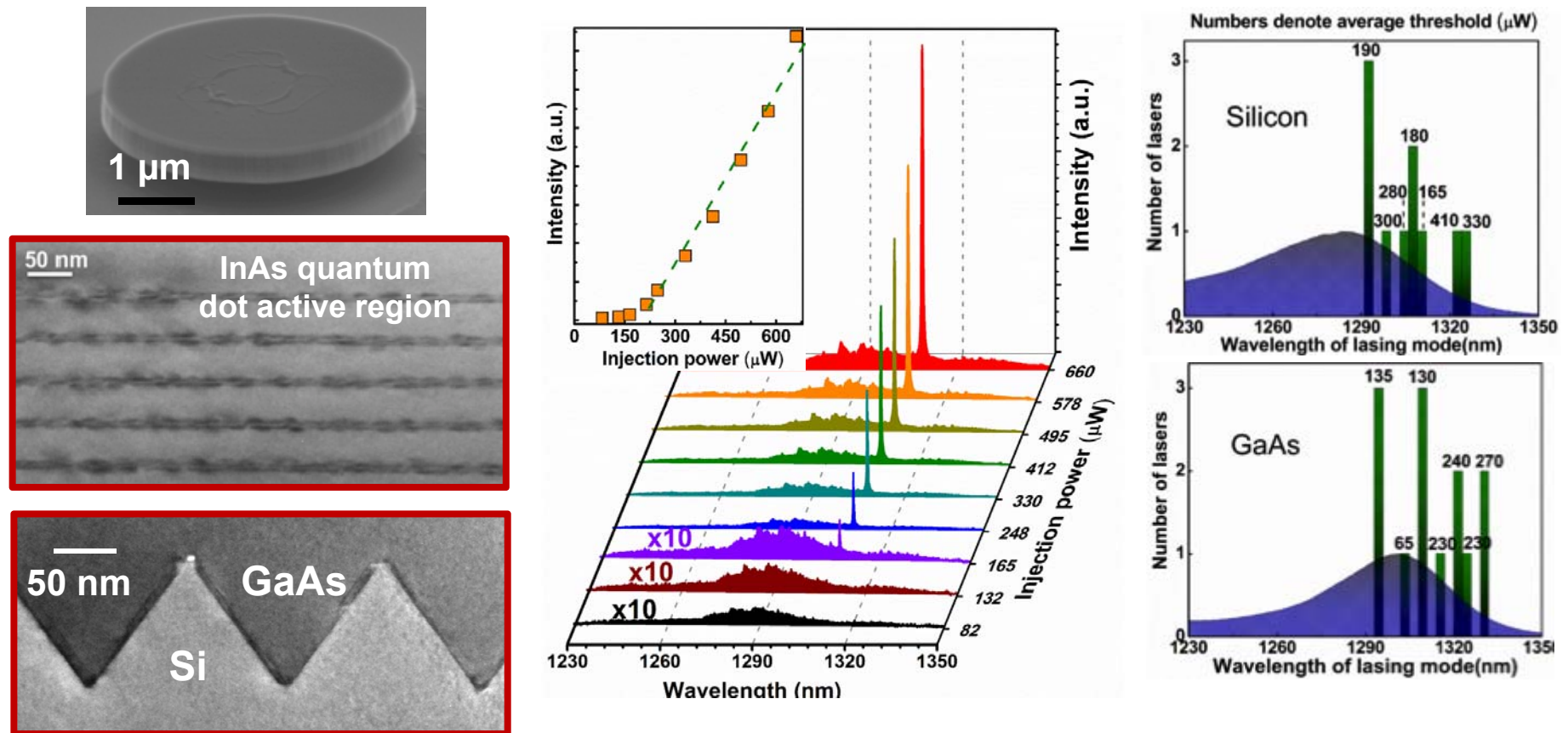
UCL: Electrically pumped continuous-wave III-V quantum dot lasers on silicon



UCSB Quantum dot microdisk lasers on (001) silicon

HKUST, UCSB, Harvard

- GaAs grown on v-groove patterned Si to filter defects (**no Ge, no offset**)
- 4 μm microdisk resonators with air cladding
- **Room temperature continuous wave lasing** observed with average thresholds of 250 μW for devices on Si substrate compared to 180 μW for devices on GaAs



Y. Wan, Q. Li, A. Y. Liu, A. C. Gossard, J. E. Bowers, E. L. Hu, K. M. Lau, "1.3 μm room temperature InAs quantum-dot micro-disk lasers directly grown on (001) silicon," Optics Letters 2016

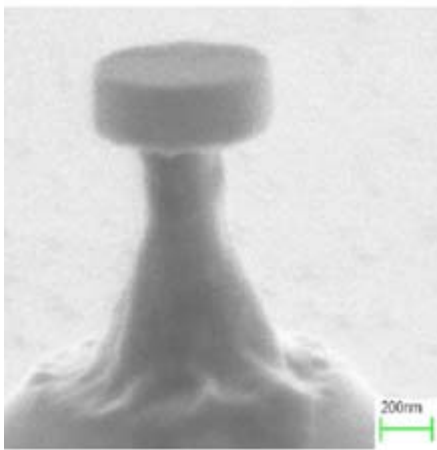
Sub wavelength quantum dot microdisk lasers on (001) silicon: HKUST, UCSB, Harvard

- Dense integration
- Low power consumption



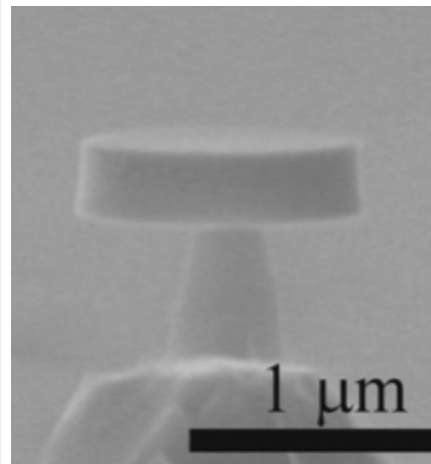
- High radiation loss
- Limited gain medium

0.86 μm / 10 K / pulse



Song et al. 2009

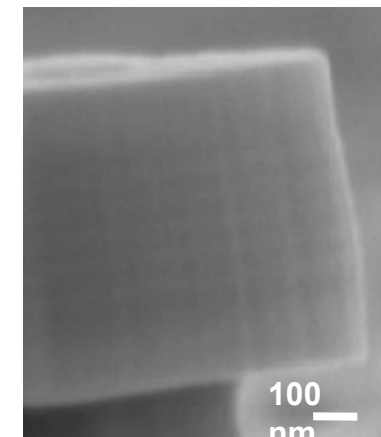
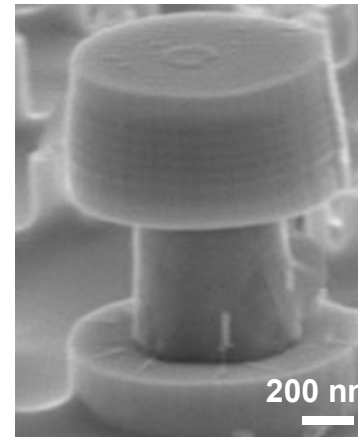
1.3 μm / 300 K /CW



**Kryzhanovskaya
et al. 2015**

Limited results on GaAs

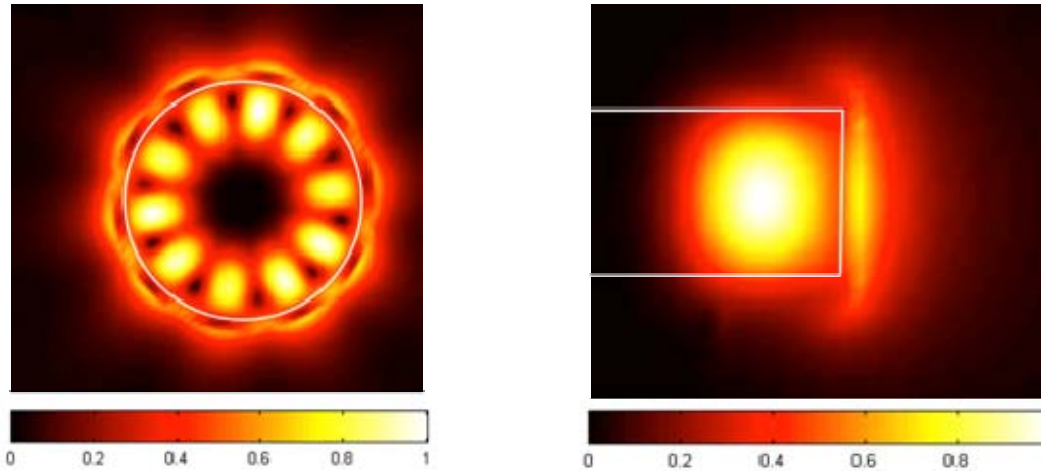
1.2 μm / 10 K /CW



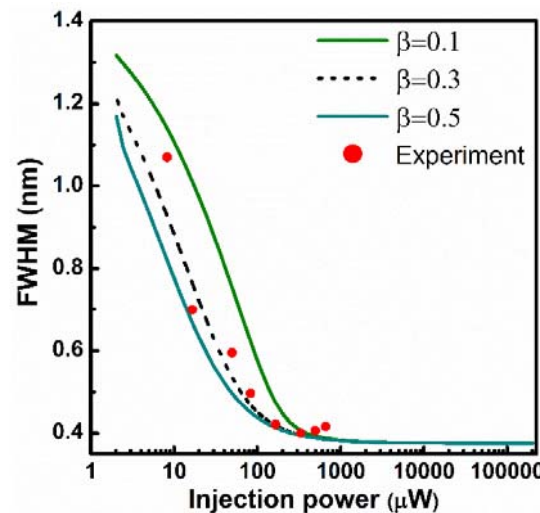
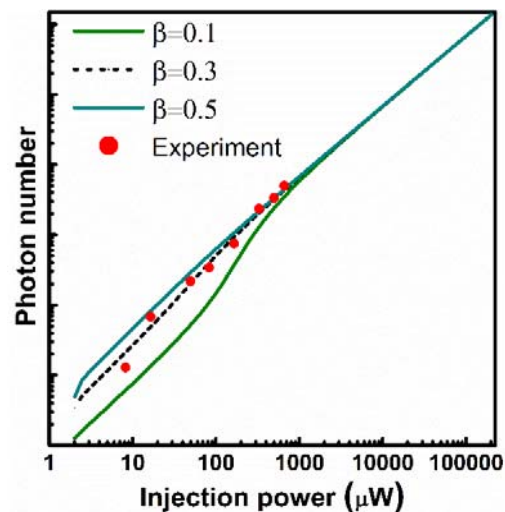
Kei May Lau et al., ThA7 ISLC 2016

First results on Si

- The lasing mode was identified to be $TE_{1,5}$ according to FDTD simulation



- The spontaneous emission factor (β) was extracted to be 0.3 by fitting the experimental data to a semiconductor cavity-QED model



Y. Wan, Q. Li, A. Y. Liu, W. W. Chow, A. C. Gossard, J. E. Bowers, E. L. Hu, and K. M. Lau, "[Sub-wavelength InAs quantum dot micro-disk lasers epitaxially grown on exact Si \(001\) substrates](#)", *Applied Physics Letters*, Vol. 108, 221101, May 2016



Bonding for Heterogeneous Si Photonics

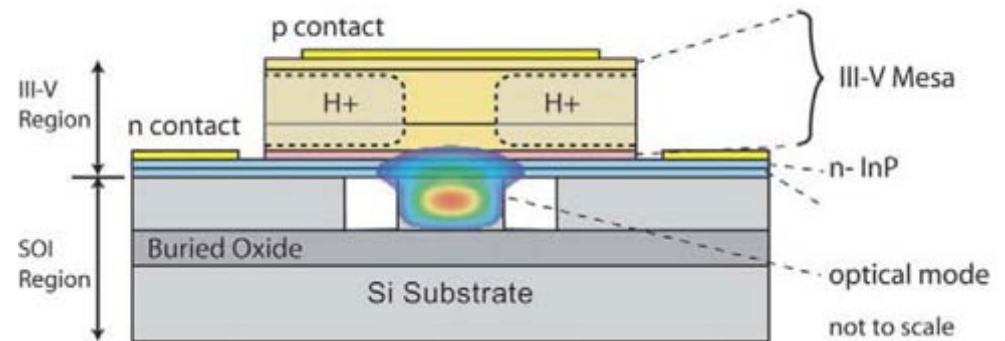
- Multiple material systems
- CMOS compatible process
- Efficient light coupling with Si WG

Full set of device library

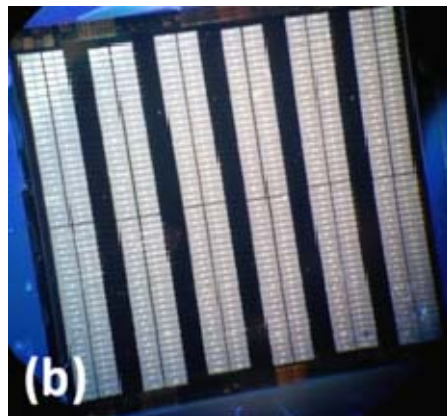
- DFB, TLD, MLL, MZM, EAM

Si_3N_4 ...

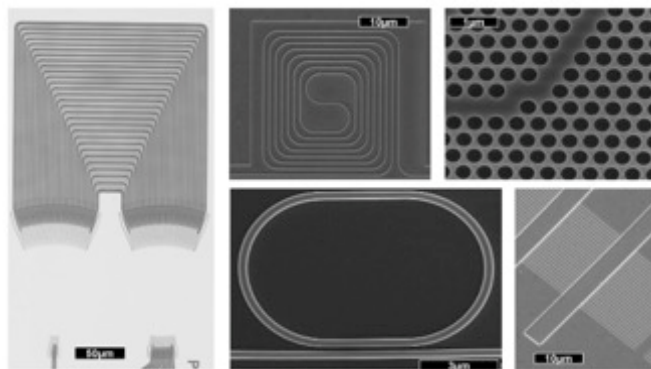
A.W. Fang, H. Park, R. Jones, O. Cohen, M. J. Paniccia, and J. E. Bowers, "A Continuous Wave Hybrid AlGaInAs-Silicon Evanescent Laser," PTL, 18 (10), 1143-1145, May 15, 2006



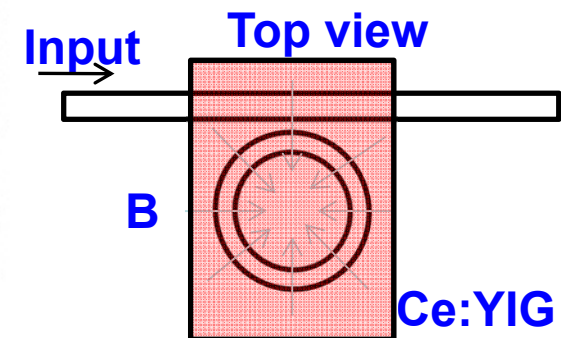
InP



Silicon

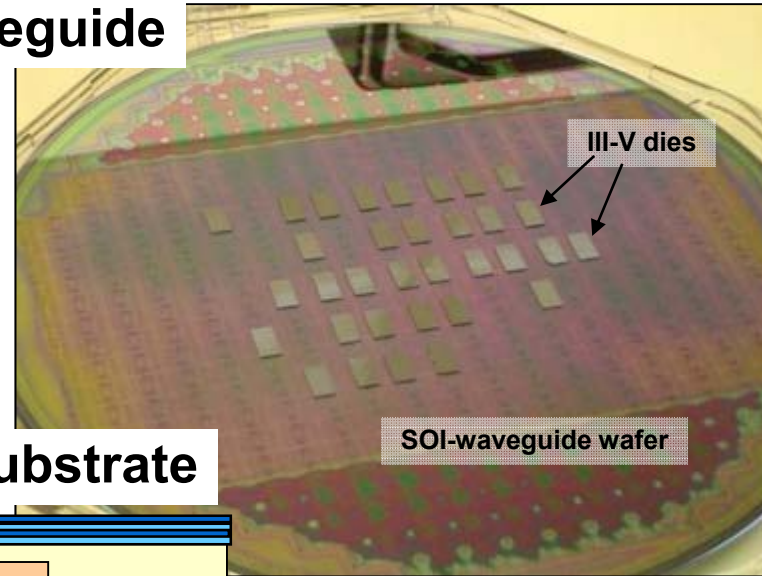
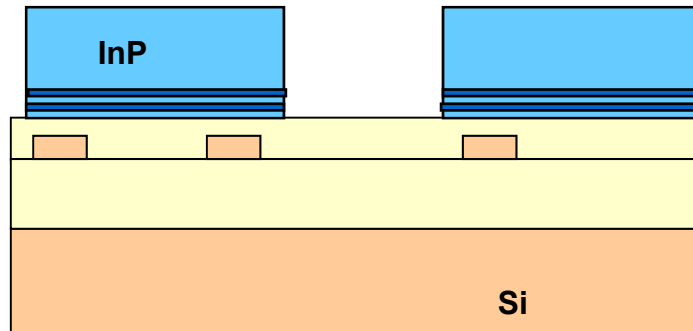


Ce:YIG
Isolator

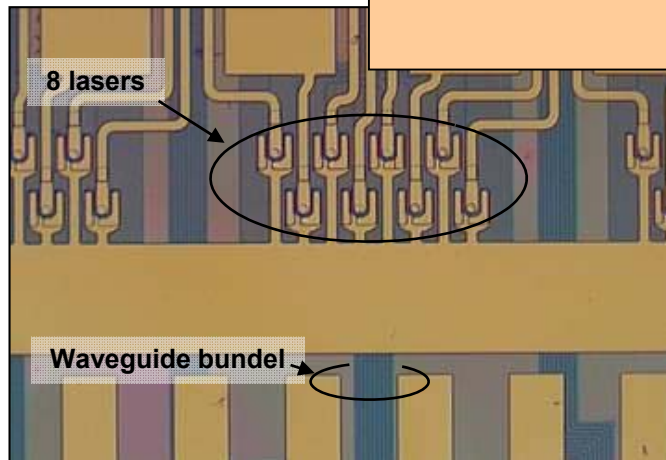
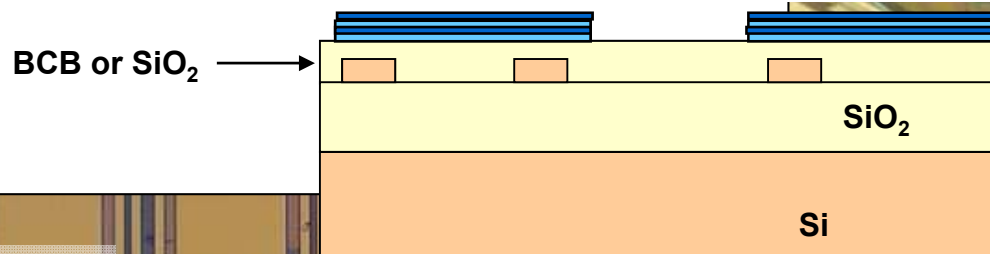


Heterogeneous integration

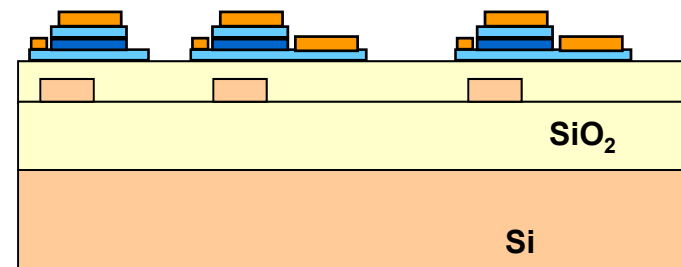
Step 1: Bond InP-dies on SOI waveguide



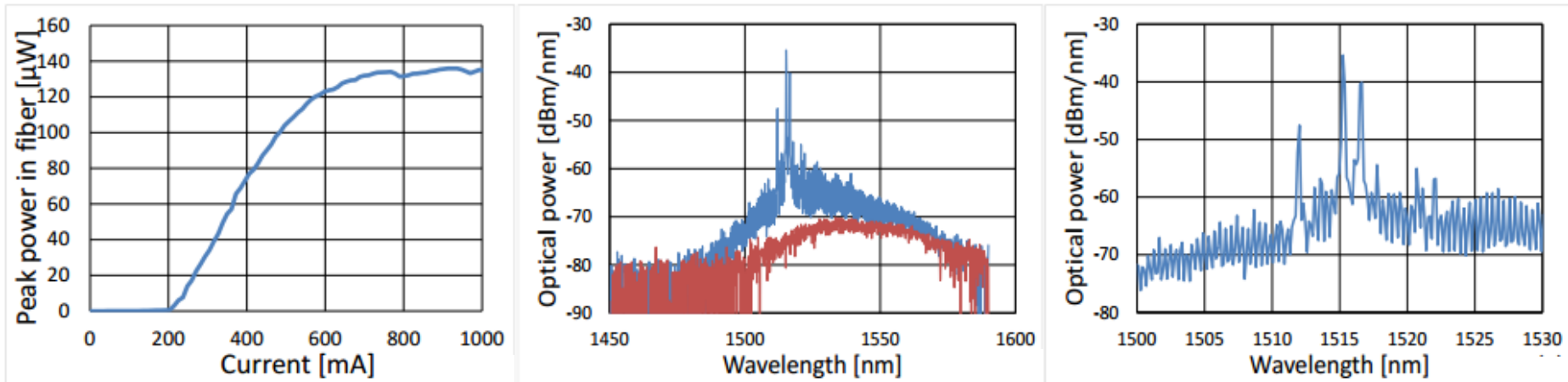
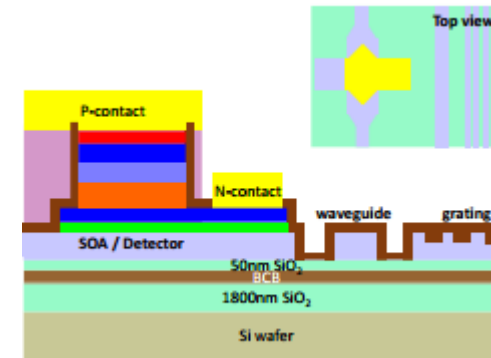
Step 2: Remove substrate



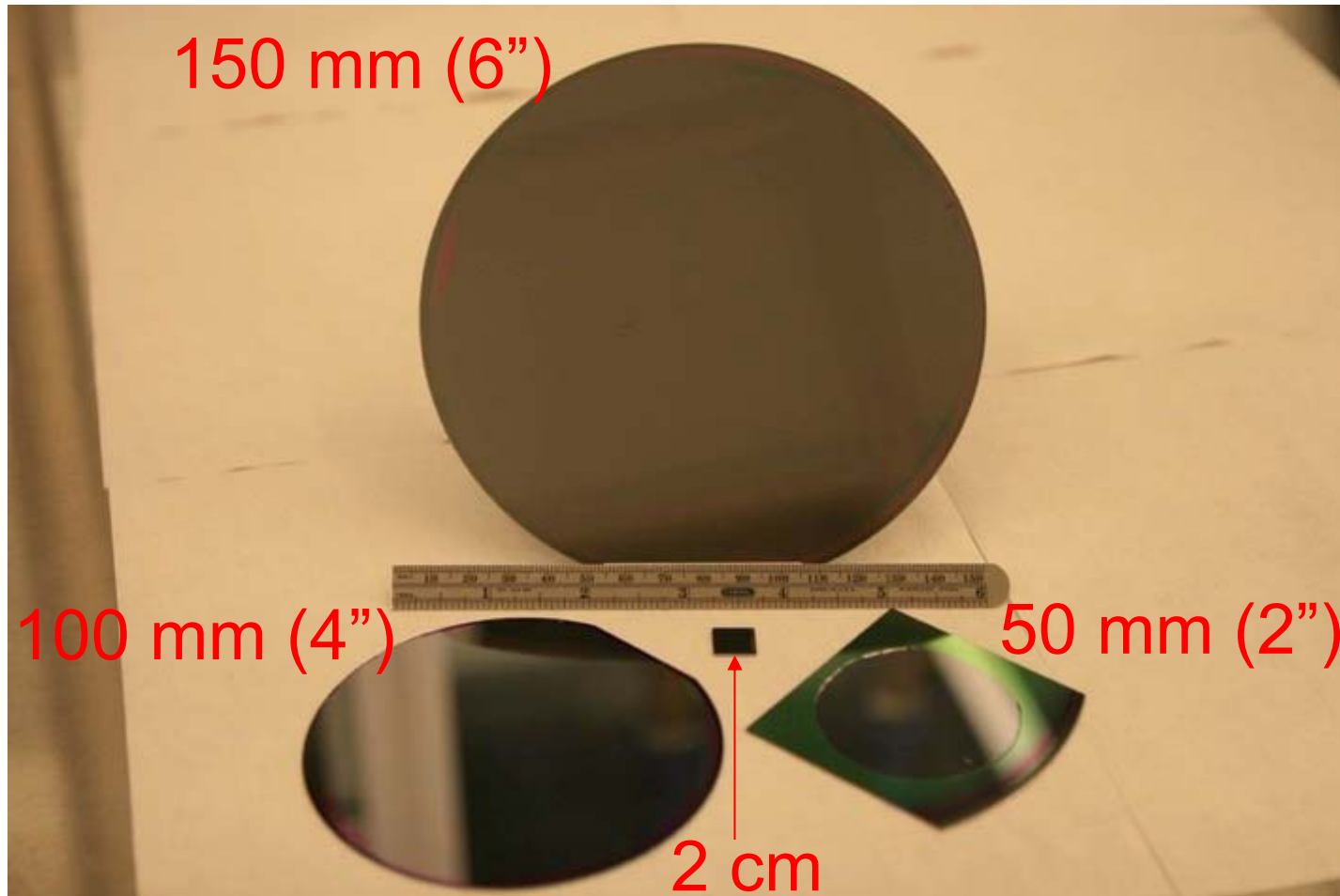
Step 3: Process lasers at wafer scale



- InP membrane on Si (IMOS)
- Bond SiO_2 to SiO_2 with BCB
- <1 mW on chip at 700 mA
- Threshold current of 200 mA
- COBRA Research Institute



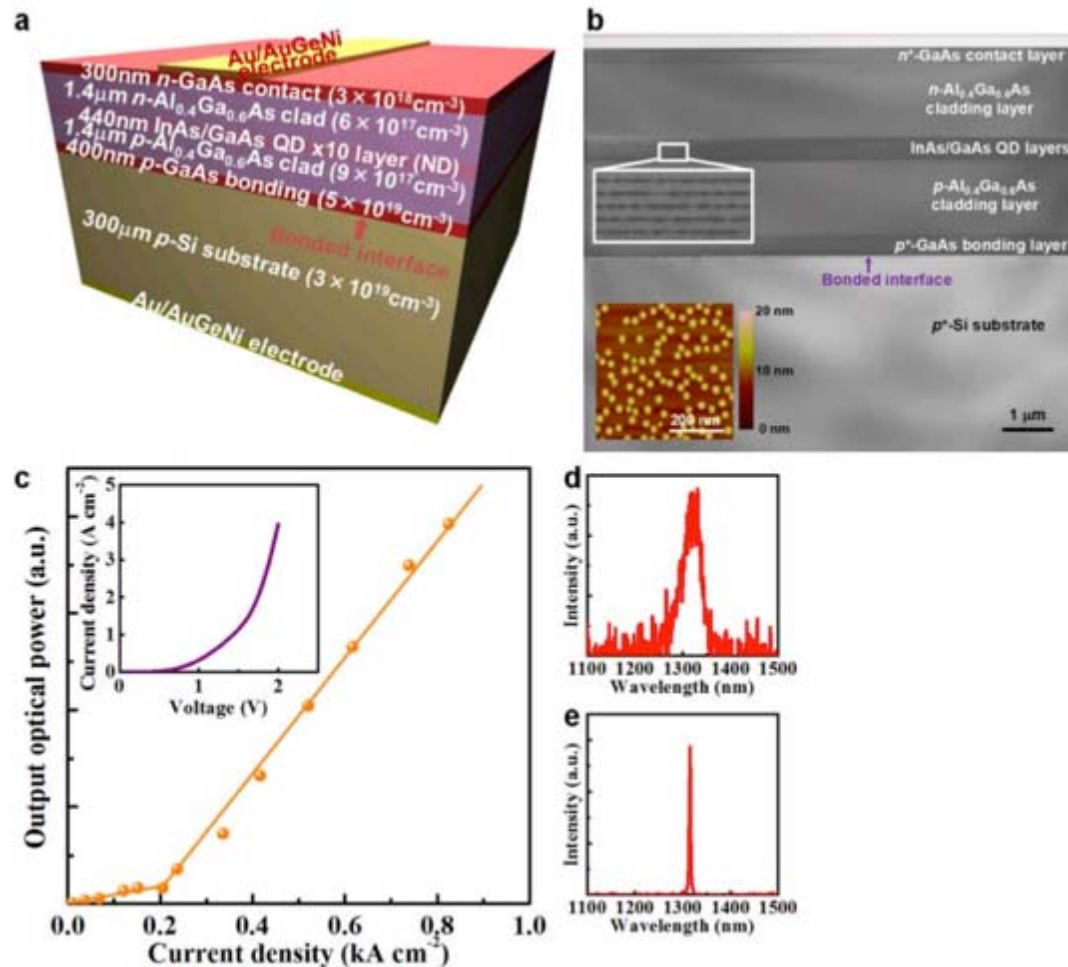
Direct Bonded Wafers



These wafers have patterned optical waveguides on SOI with 2 micron GaInAsP layer on top.

Oxygen plasma enhanced bonding: 300 C, 30 minutes

Quantum Dot Lasers on Si by Direct Fusion Bonding

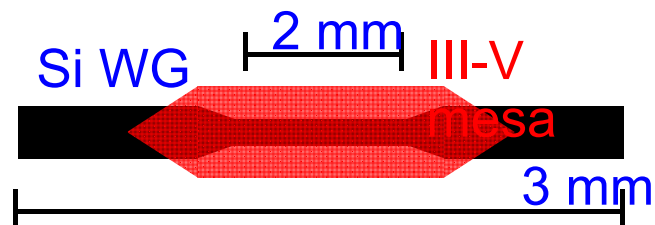


- First 1.3 μm quantum dot lasers on Si with current injection across bonded GaAs/Si interface
- Direct wafer bonding without metal or oxide mediation
- 2 nm amorphous interlayer at the bonding interface
- Threshold: **205 A/cm^2** pulsed at room temperature (for 2.1mm x 100 μm device).

Tanabe, Katsuaki, Katsuyuki Watanabe, and Yasuhiko Arakawa. "III-V/Si hybrid photonic devices by direct fusion bonding." *Scientific reports* 2 (2012).

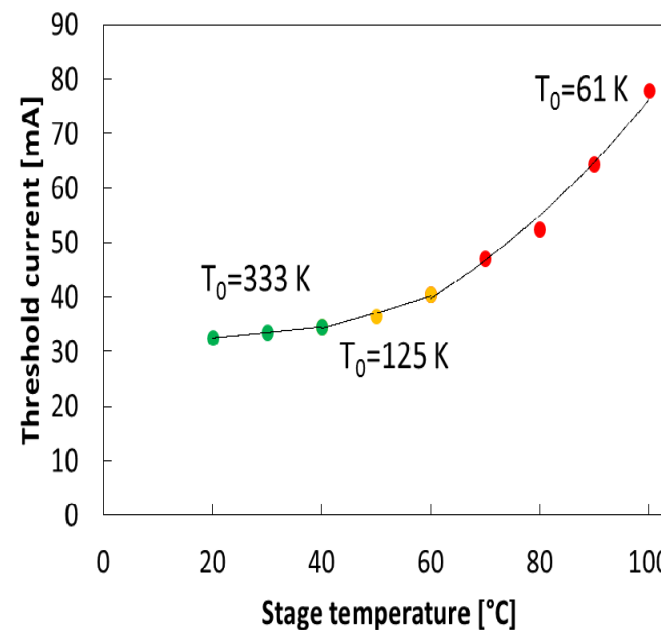
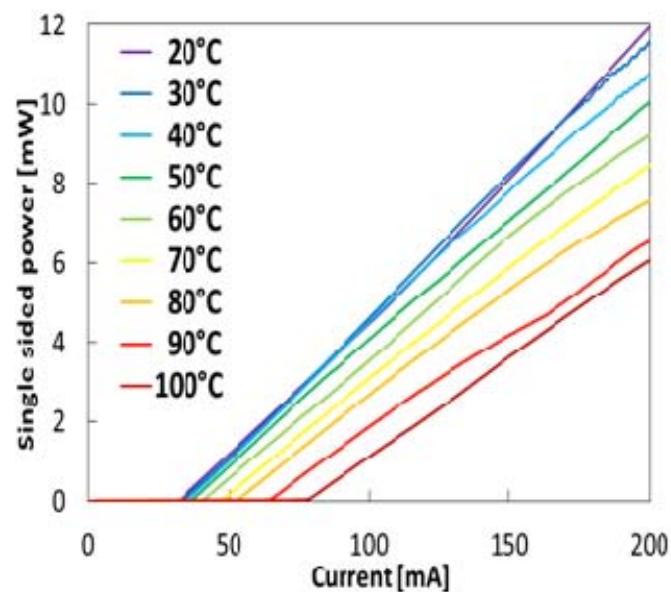
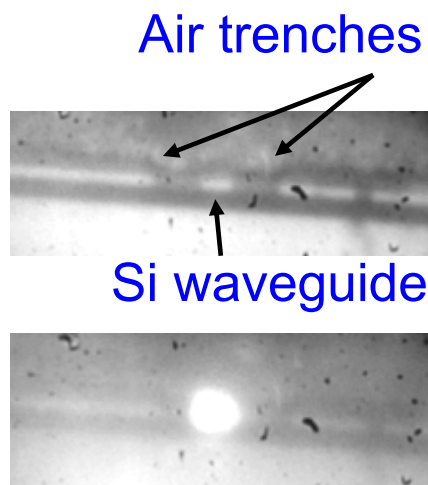
Wafer bonded QD laser on Si

HPE

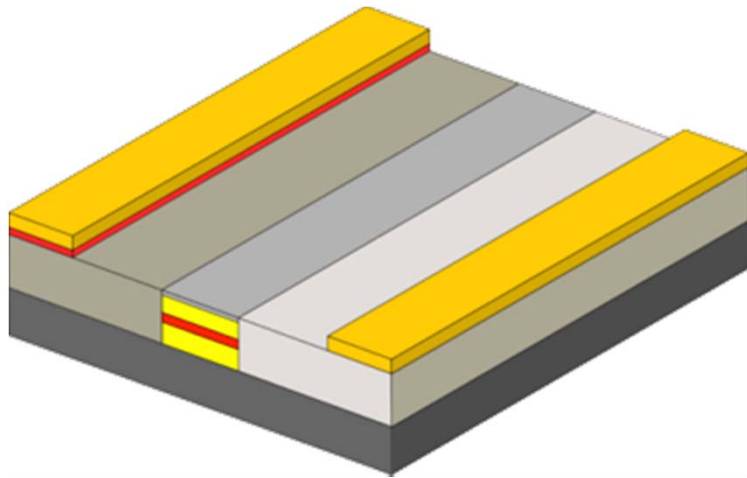


Kurczweil et al... HPE
ThA5 Thursday 9:30 am

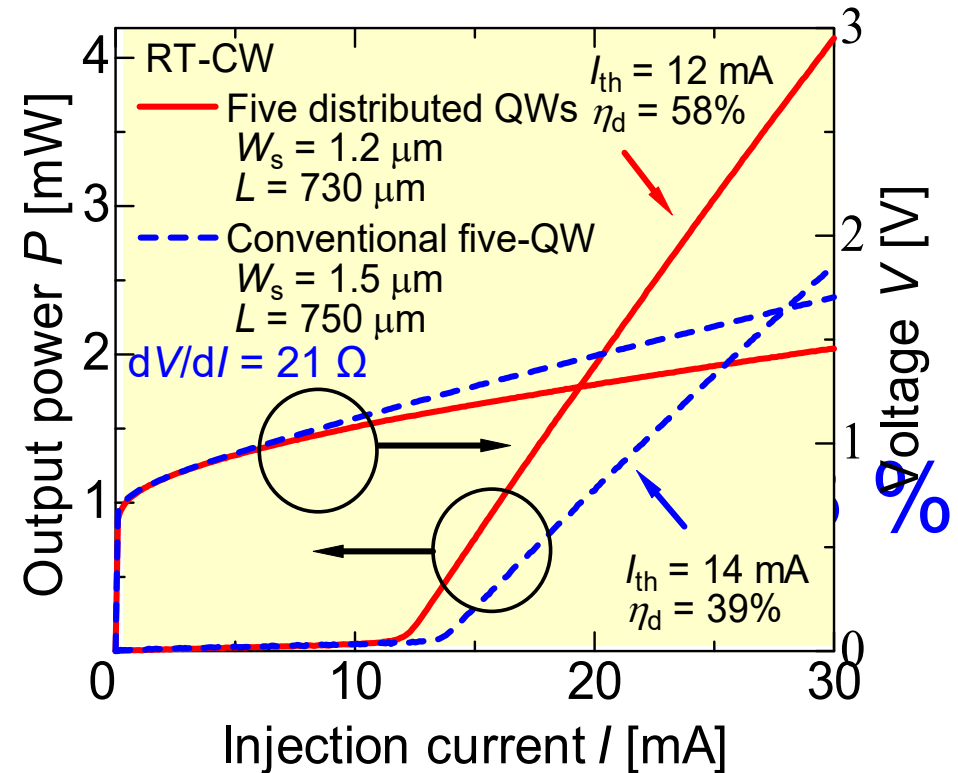
6 μm wide mesa, $\Gamma_{\text{QD}}=55\%$



Arai Plenary Tuesday 8:45 am



BCB Bonding
Single mode lasers

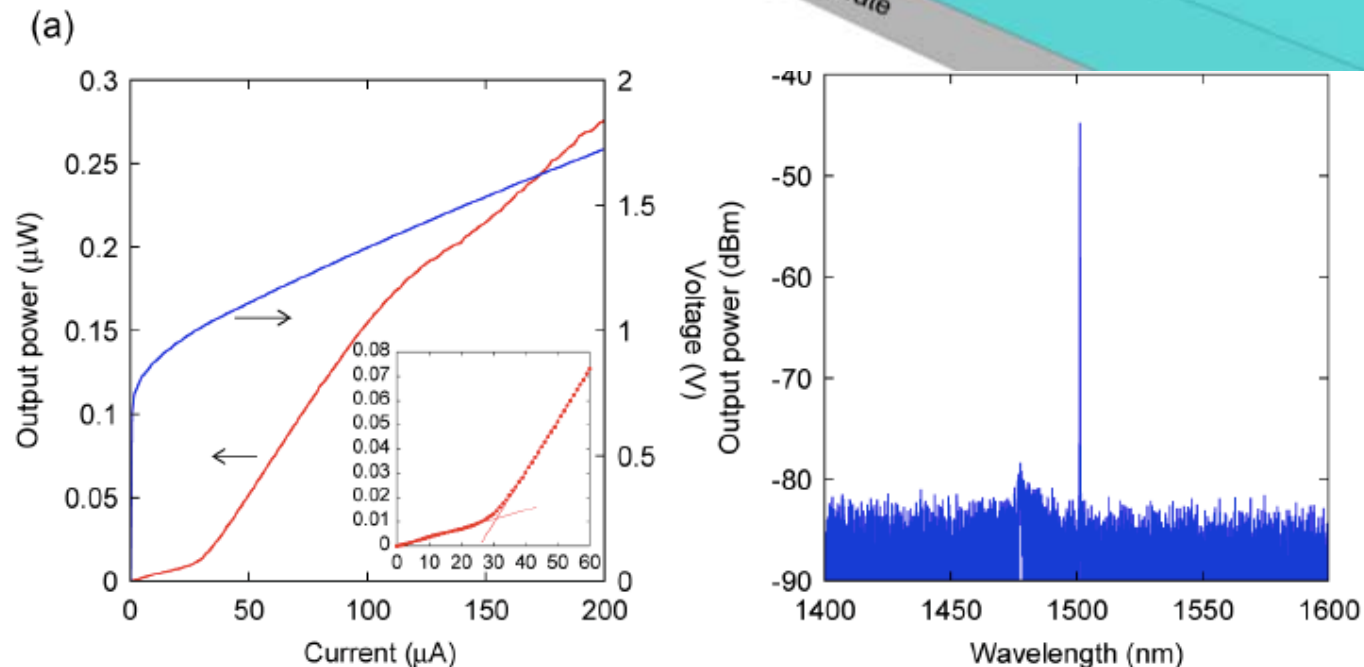
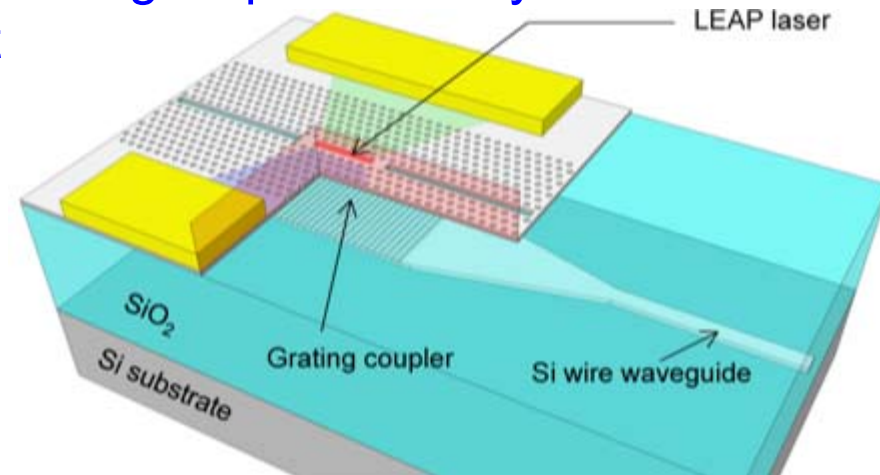


$$I_{th} = 12 \text{ mA}, \eta_d = 58\%$$

$$dV/dI = 21 \Omega (@I = 12 \text{ mA})$$

(M. Futami et. al, IEEE PTL, vol. 24, no. 11, p. 888, June 2012.)

LEAP: lambda-scale embedded active-region photonic-crystal
Photonic crystal lateral confinement
Strong SiO₂ vertical confinement
Low threshold: 42 μ A!
Low total output power
Single mode operation

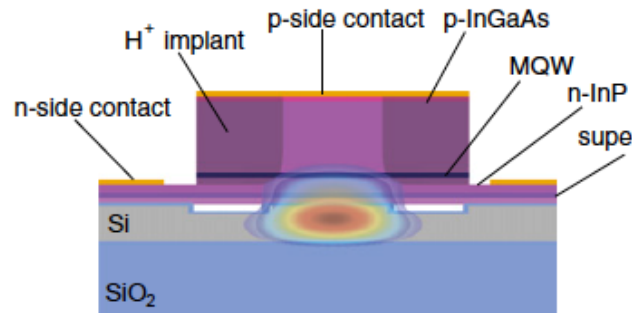


K. Takada et al. Optics Express (2015).

High-coherence semiconductor lasers based on integral high- Q resonators in hybrid Si/III-V platforms

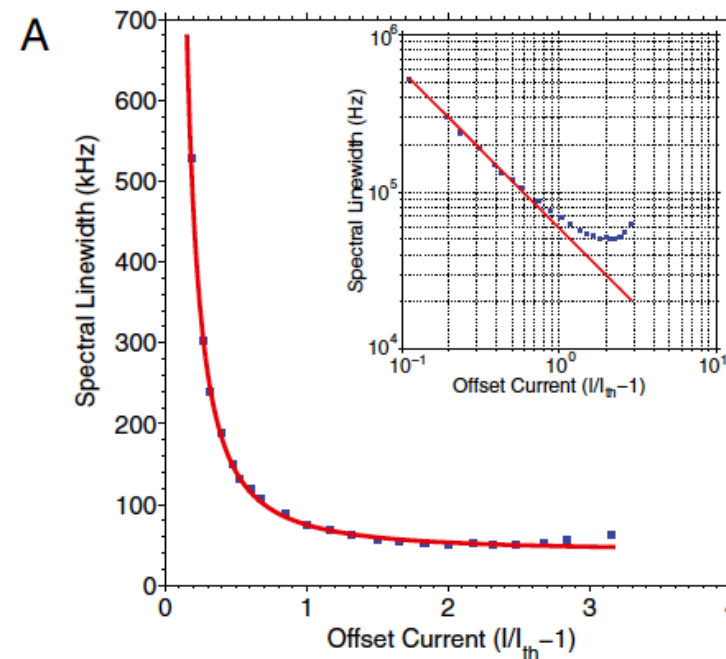
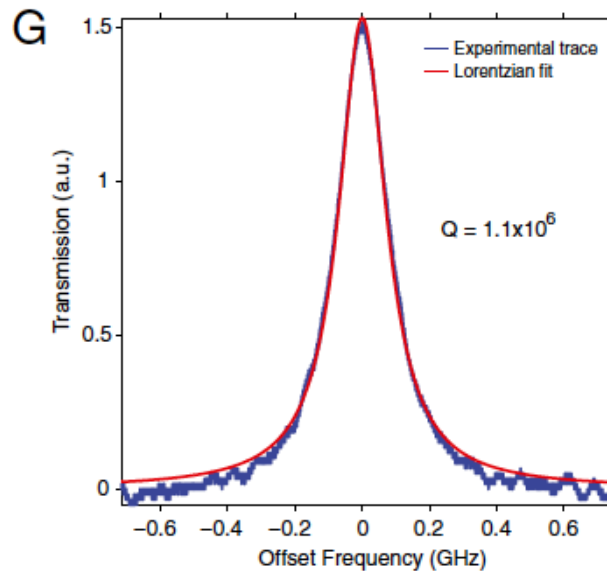
Christos Theodoros Santis¹, Scott T. Steger, Yaakov Vilenchik, Arseny Vasilyev, and Amnon Yariv¹

Yariv Plenary Tuesday 8 am

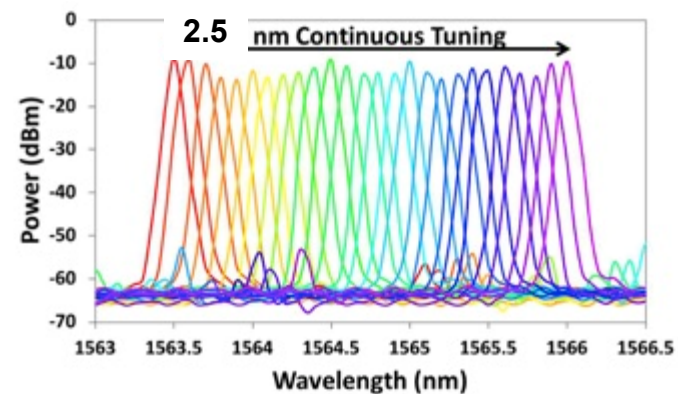
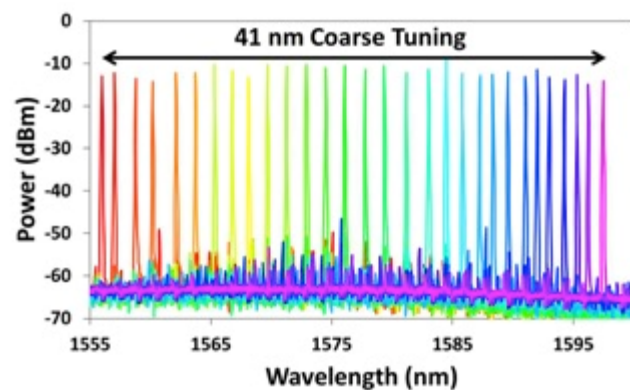
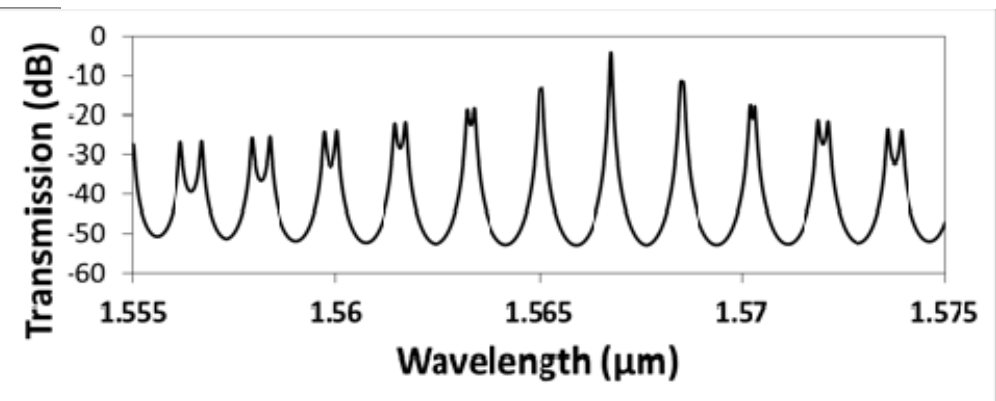
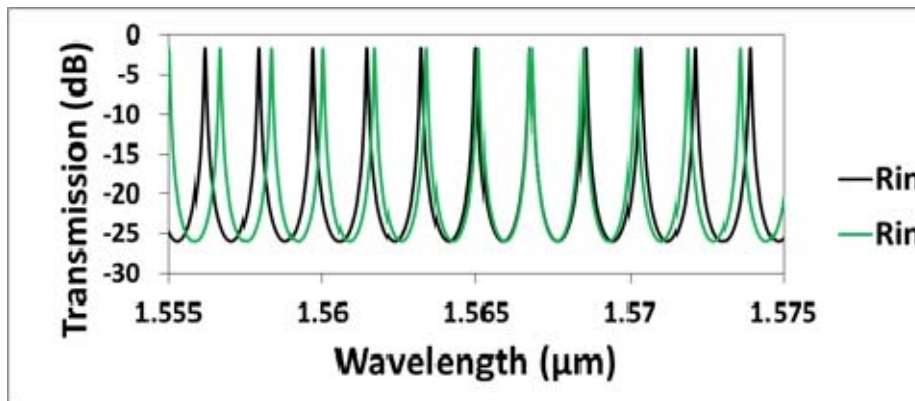
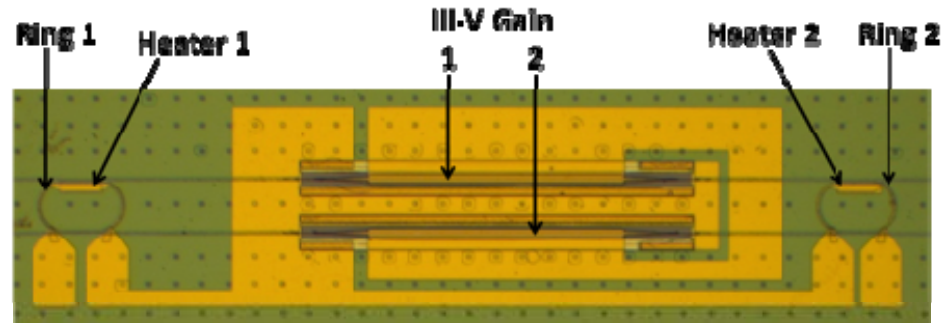
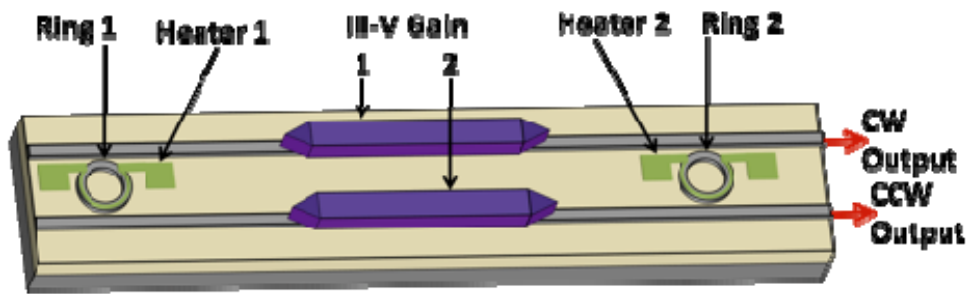


$$(\Delta\nu)_{laser} = \frac{2\pi h\nu_o^3 \mu(1 + \alpha^2)}{Q^2 P}$$

High Q (1 million)
1 kHz linewidth

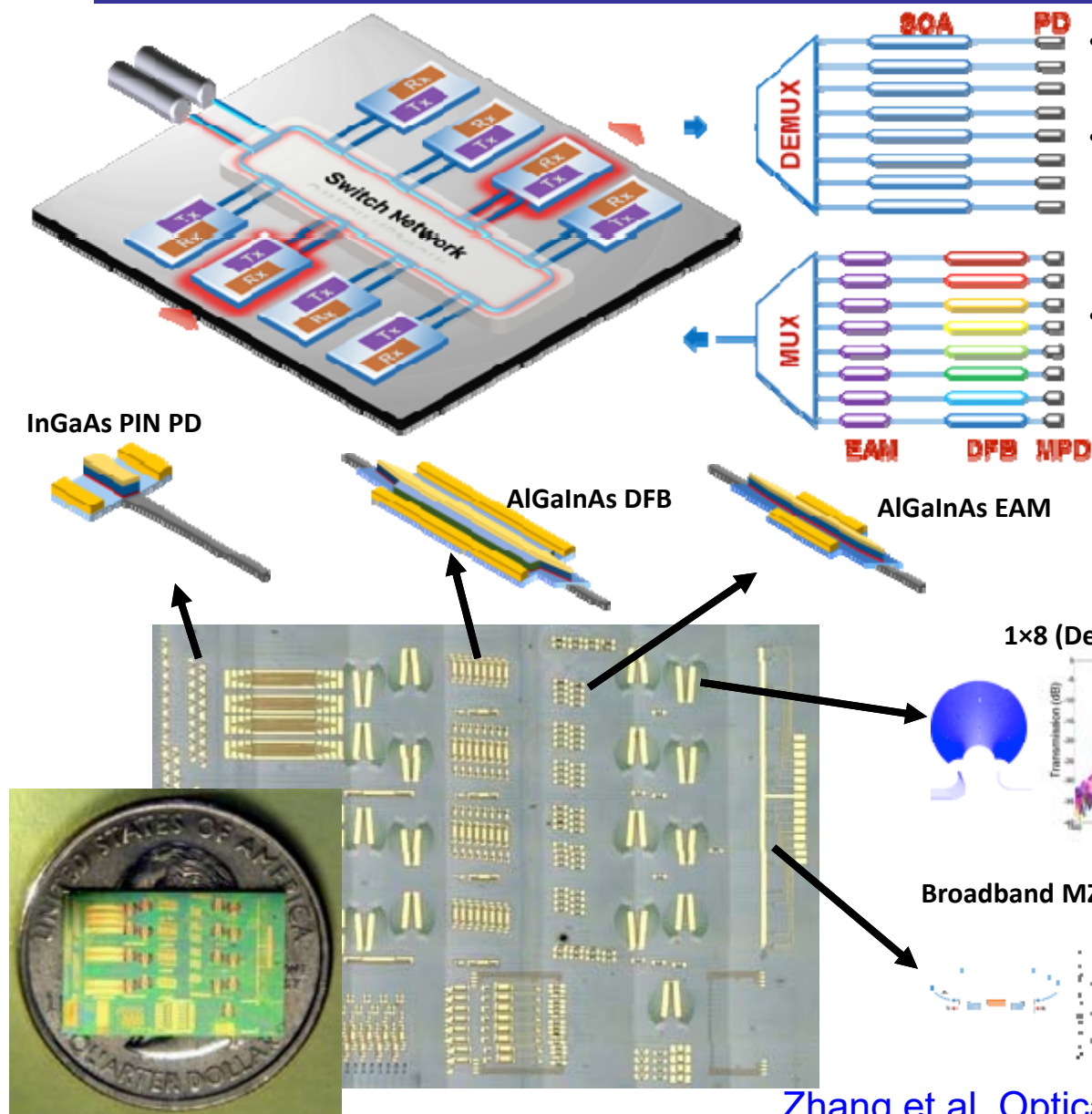


Widely Tunable Vernier Ring Laser



Heterogeneously-integrated WDM Network-on-Chip

UCSB

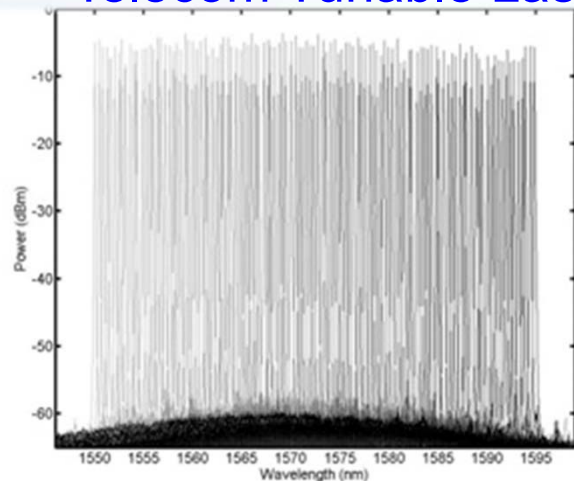


- Fully integrated WDM transceiver network
- Compact footprint with 300+ active units (48 DFB, 93 EAM, 67 PD) and 120+ passive units (7 AWG, 1X15 MZI switch) in single chip;
- Data rate of 40 Gbps per wavelength channel, showing a potential large capacity of the transceiver array, with 320 (8×40) Gbps per transceiver node, and 2.56 Tbps (8×320 Gbps) for the whole photonic circuit.

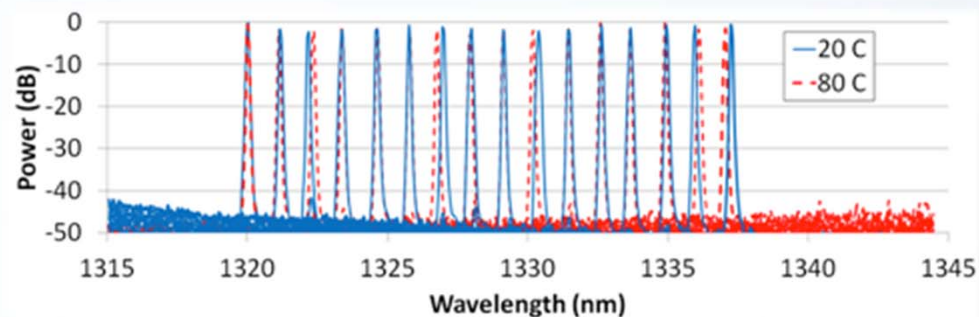
Aurion PIC Integration

Brian Koch *et al.*, OFC Postdeadline 2013

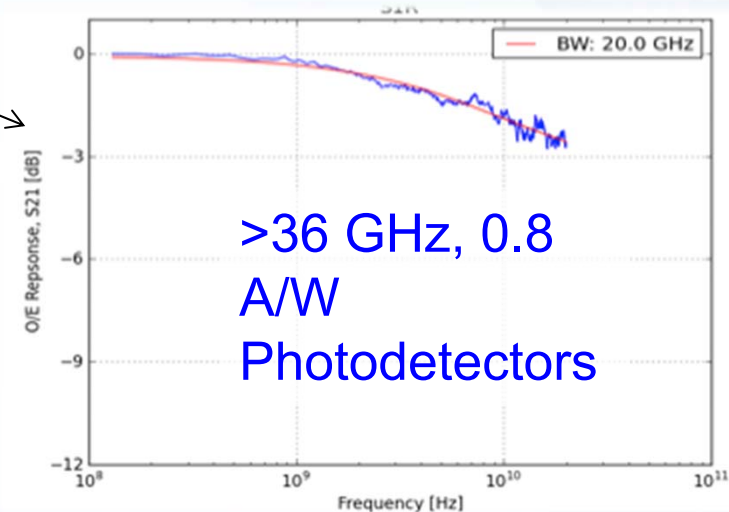
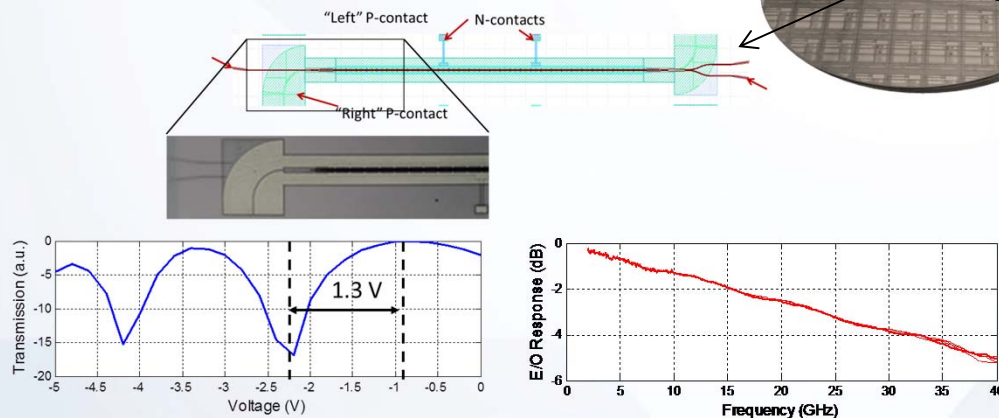
Telecom Tunable Lasers



Datacom uncooled WDM laser arrays



Modulators: 23 GHz, >15 dB ER



Intel is shipping heterogeneous PICs in high volume production for 100 Gbps

Intel® Silicon Photonics Products

These optical transceivers enable high-bandwidth connections reaching up to 2km over single-mode fiber, based on industry standards at 100G for switch, router, and server use.



100G PSM4 QSFP28 Optical Transceiver

Features up to 2km reach on parallel single-mode fiber, and is designed to be compliant with 100G PSM4 MSA, QSFP28, and CAUI-4 specifications.

[Read the product brief ›](#)



100G CWDM4 QSFP28 Optical Transceiver

Features up to 2km reach on duplex single-mode fiber, with high speed and low-power consumption. Designed to be compliant with 100G CWDM4 and CLR4 MSA, QSFP28, and CAUI-4 specifications.³

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Summary

- Complicated, high performance PICs are being commercialized on silicon substrates (Intel, Acacia, Juniper Networks, Mellonix, Oracle,...)
- Lasers on silicon are here at low cost.
- Highest level of integration on silicon: >400 elements on chip, including 64 low threshold lasers on chip
- Fully integrated reconfigurable photonic network for chip-level interconnection, total capacity up to 2.56 Tbps

